

FEATURES

- ARM720T Processor
 - ARM7TDMI CPU
 - 8 KB of four-way set-associative cache
 - MMU with 64-entry TLB
 - Thumb code support enabled
- Ultra low power
 - 90 mW at 74 MHz typical
 - 30 mW at 18 MHz typical
 - 10 mW in the Idle State
 - <1 mW in the Standby State
- Advanced audio decoder/decompression capability
 - Supports bit streams with adaptive bit rates
 - Allows for support of multiple audio decompression algorithms (MP3, WMA, AAC, ADPCM, Audible, etc.)



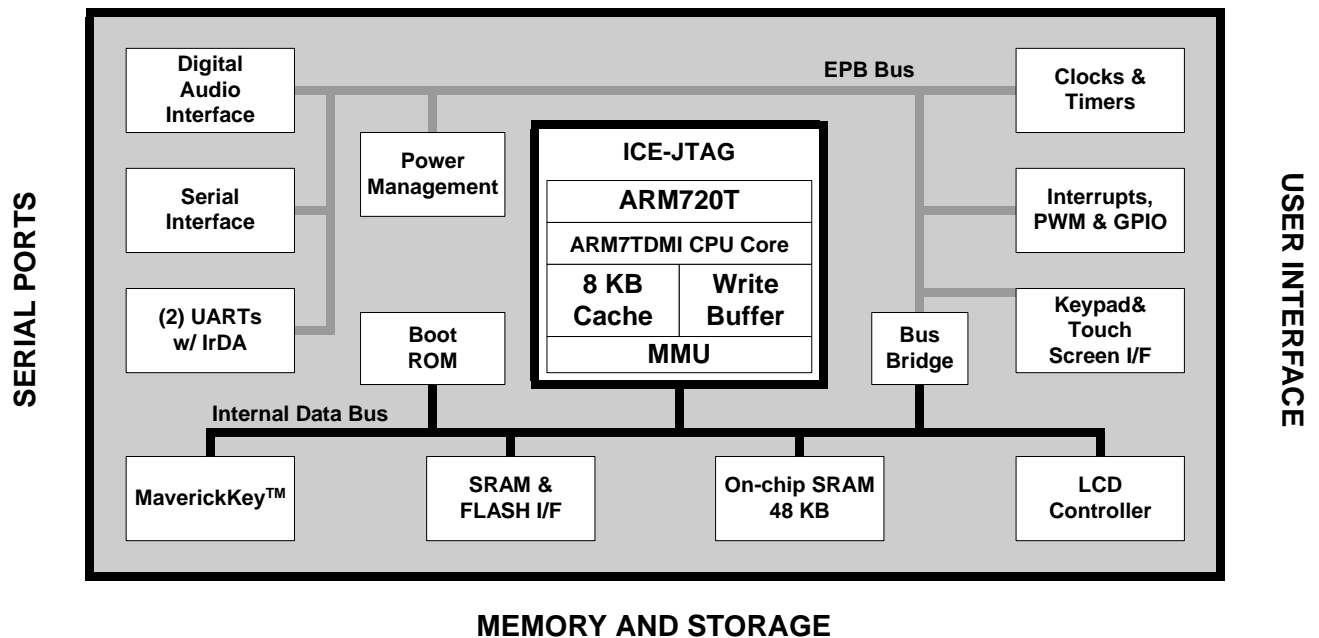
**High-performance,
Low-power, System-on-chip
with Enhanced
Digital Audio Interface**

OVERVIEW

The Maverick™ EP7309 is designed for ultra-low-power applications such as digital music players, internet appliances, smart cellular phones or any hand-held device that features the added capability of digital audio decompression. The core-logic functionality of the device is built around an ARM720T processor with 8 KB of four-way set-associative unified cache and a write buffer. Incorporated into the ARM720T is an enhanced memory management unit (MMU) which allows for support of sophisticated operating systems like Microsoft® Windows® CE and Linux®.

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BLOCK DIAGRAM

MEMORY AND STORAGE

FEATURES (cont)

Dynamically programmable clock speeds of 18, 36, 49, and 74 MHz

48 KB of on-chip SRAM

MaverickKey™ IDs

- 32-bit unique ID can be used for SDMI compliance
- 128-bit random ID

LCD controller

- Interfaces directly to a single-scan panel monochrome STN LCD
- Interfaces to a single-scan panel color STN LCD with minimal external glue logic

Full JTAG boundary scan and Embedded ICE® support

Integrated Peripheral Interfaces

- 8/32/16-bit SRAM/FLASH/ROM Interface
- Digital Audio Interface providing glueless interface to low-power DACs, ADCs and CODECs
- Two Synchronous Serial Interfaces (SSI1, SSI2)

— CODEC Sound Interface

— 8×8 Keypad Scanner

— 27 General Purpose Input/Output pins

— Dedicated LED flasher pin from the RTC

Internal Peripherals

— Two 16550 compatible UARTs

— IrDA Interface

— Two PWM Interfaces

— Real-time Clock

— Two general purpose 16-bit timers

— Interrupt Controller

— Boot ROM

Package

— 208-Pin LQFP

— 256-Ball PBGA

The fully static EP7309 is optimized for low power dissipation and is fabricated on a 0.25 micron CMOS process

OVERVIEW (cont.)

The EP7309 is designed for ultra-low-power operation. Its core operates at only 2.5 V, while its I/O has an operation range of 2.5 V–3.3 V. The device has three basic power states: operating, idle and standby.

MaverickKey unique hardware programmed IDs are a solution to the growing concern over secure web content and commerce. With Internet security playing an important role in the delivery of digital media such as books or music, traditional software methods are quickly becoming unreliable. The MaverickKey unique IDs provide OEMs with a method of utilizing specific hardware IDs such as those assigned for SDMI (Secure Digital Music Initiative) or any other authentication mechanism.

The EP7309 integrates an interface to enable a direct connection to many low cost, low power, high quality audio converters. In particular, the DAI can directly interface with the Crystal, CS43L41/42/43 low-power audio DACs and the Crystal, CS53L32 low-power ADC. Some of these devices feature digital bass and treble boost, digital volume control and compressor-limiter functions.

Simply by adding desired memory and peripherals to the highly integrated EP7309 completes a low-power system solution. All necessary interface logic is integrated on-chip.

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Processor Core - ARM720T

The EP7309 incorporates an ARM 32-bit RISC microcontroller that controls a wide range of on-chip peripherals. The processor utilizes a three-stage pipeline consisting of fetch, decode and execute stages. Key features include:

- ARM (32-bit) and Thumb (16-bit compressed) instruction sets
- Enhanced MMU for Microsoft Windows CE and other operating systems
- 8 KB of 4-way set-associative cache.
- Translation Look Aside Buffers with 64 Translated Entries

Power Management

The EP7309 is designed for ultra-low-power operation. Its core operates at only 2.5 V, while its I/O has an operation range of 2.5 V–3.3 V allowing the device to achieve a performance level equivalent to 60 MIPS. The device has three basic power states:

- Operating — This state is the full performance state. All the clocks and peripheral logic are enabled.
- Idle — This state is the same as the Operating State, except the CPU clock is halted while waiting for an event such as a key press.
- Standby — This state is equivalent to the computer being switched off (no display), and the main oscillator shut down. An event such as a key press can wake-up the processor.

| Pin Mnemonic | I/O | Pin Description |
|--------------|-----|-----------------------------------|
| BATOK | I | Battery ok input |
| nEXTPWR | I | External power supply sense input |
| nPWFL | I | Power fail sense input |
| nBATCHG | I | Battery changed sense input |

Table 1. Power Management Pin Assignments

MaverickKey™ Unique ID

MaverickKey unique hardware programmed IDs are a solution to the growing concern over secure web content and commerce. With Internet security playing an important role in the delivery of digital media such as books or music, traditional software methods are quickly becoming unreliable. The MaverickKey unique IDs provide OEMs with a method of utilizing specific hardware IDs such as those assigned for SDMI (Secure Digital Music Initiative) or any other authentication mechanism.

Both a specific 32-bit ID as well as a 128-bit random ID is programmed into the EP7309 through the use of laser probing technology. These IDs can then be used to match secure copyrighted content with the ID of the target device the EP7309 is powering, and then deliver the copyrighted information over a secure connection. In addition, secure transactions can benefit by also matching device IDs to server IDs. MaverickKey IDs provide a level of hardware security required for today's Internet appliances.

Memory Interfaces

The EP7309 is equipped with a ROM/SRAM/FLASH-style interface that has programmable wait-state timings and includes burst-mode capability, with six chip selects decoding six 256 MB sections of addressable space. For maximum flexibility, each bank can be specified to be 8-, 16-, or 32-bits wide. This allows the use of 8-bit-wide boot ROM options to minimize overall system cost. The on-chip boot ROM can be used in product manufacturing to serially download system code into system FLASH memory. To further minimize system memory requirements and cost, the ARM Thumb instruction set is supported, providing for the use of high-speed 32-bit operations in 16-bit op-codes and yielding industry-leading code density.

| Pin Mnemonic | I/O | Pin Description |
|--------------|-----|-------------------------------|
| nCS[5:0] | O | Chip select out |
| A[27:0] | O | Address output |
| D[31:0] | I/O | Data I/O |
| nMOE | O | ROM expansion OP enable |
| nMWE | O | ROM expansion write enable |
| HALFWORD | O | Halfword access select output |
| WORD | O | Word access select output |
| WRITE | O | Transfer direction |

Table 2. Static Memory Interface Pin Assignments

Digital Audio Capability

The EP7309 uses its powerful 32-bit RISC processing engine to implement audio decompression algorithms in software. The nature of the on-board RISC processor, and the availability of efficient C-compilers and other software development tools, ensures that a wide range of audio decompression algorithms can easily be ported to and run on the EP7309

Universal Asynchronous Receiver/Transmitters (UARTs)

The EP7309 includes two 16550-type UARTs for RS-232 serial communications, both of which have two 16-byte FIFOs for receiving and transmitting data. The UARTs support bit

rates up to 115.2 kbps. An IrDA SIR protocol encoder/decoder can be optionally switched into the RX/TX signals to/from UART 1 to enable these signals to drive an infrared communication interface directly.

| Pin Mnemonic | I/O | Pin Description |
|--------------|-----|----------------------------|
| TXD[1] | O | UART 1 transmit |
| RXD[1] | I | UART 1 receive |
| CTS | I | UART 1 clear to send |
| DCD | I | UART 1 data carrier detect |
| DSR | I | UART 1 data set ready |
| TXD[2] | O | UART 2 transmit |
| RXD[2] | I | UART 2 receive |
| LEDDRIV | O | Infrared LED drive output |
| PHDIN | I | Photo diode input |

Table 3. Universal Asynchronous Receiver/Transmitters Pin Assignments

Digital Audio Interface (DAI)

The EP7309 integrates an interface to enable a direct connection to many low cost, low power, high quality audio converters. In particular, the DAI can directly interface with the Crystal CS43L41/42/43 low-power audio DACs and the Crystal CS53L32 low-power ADC. Some of these devices feature digital bass and treble boost, digital volume control and compressor-limiter functions.

| Pin Mnemonic | I/O | Pin Description |
|--------------|-----|---------------------|
| SCLK | O | Serial bit clock |
| SDOUT | O | Serial data out |
| SDIN | I | Serial data in |
| LRCK | O | Sample clock |
| MCLKIN | I | Master clock input |
| MCLKOUT | O | Master clock output |

Table 4. DAI Interface Pin Assignments

Note: See [Table 17 on page 10](#) for information on pin multiplexes.

CODEC Interface

The EP7309 includes an interface to telephony-type CODECs for easy integration into voice-over-IP and other voice

communications systems. The CODEC interface is multiplexed to the same pins as the DAI and SSI2.

| Pin Mnemonic | I/O | Pin Description |
|--------------|-----|------------------|
| PCMCLK | O | Serial bit clock |
| PCMOUT | O | Serial data out |
| PCMIN | I | Serial data in |
| PCMSYNC | O | Frame sync |

Table 5. CODEC Interface Pin Assignments

Note: See [Table 17 on page 10](#) for information on pin multiplexes.

SSI2 Interface

An additional SPI/Microwire1-compatible interface is available for both master and slave mode communications. The SSI2 unit shares the same pins as the DAI and CODEC interfaces through a multiplexer.

- Synchronous clock speeds of up to 512 kHz
- Separate 16 entry TX and RX half-word wide FIFOs
- Half empty/full interrupts for FIFOs
- Separate RX and TX frame sync signals for asymmetric traffic

| Pin Mnemonic | I/O | Pin Description |
|--------------|-----|---------------------|
| SSICLK | I/O | Serial bit clock |
| SSITXDA | O | Serial data out |
| SSIRXDA | I | Serial data in |
| SSITXFR | I/O | Transmit frame sync |
| SSIRXFR | I/O | Receive frame sync |

Table 6. SSI2 Interface Pin Assignments

Note: See [Table 17 on page 10](#) for information on pin multiplexes.

Synchronous Serial Interface

- ADC (SSI) Interface: Master mode only; SPI and Microwire1-compatible (128 kbps operation)
- Selectable serial clock polarity

| Pin Mnemonic | I/O | Pin Description |
|--------------|-----|------------------------|
| ADCLK | O | SSI1 ADC serial clock |
| ADCIN | I | SSI1 ADC serial input |
| ADCOUT | O | SSI1 ADC serial output |
| nADCCS | O | SSI1 ADC chip select |
| SMPCLK | O | SSI1 ADC sample clock |

Table 7. Serial Interface Pin Assignments

LCD Controller

A DMA address generator is provided that fetches video display data for the LCD controller from memory. The display frame buffer start address is programmable, allowing the LCD frame buffer to be in SDRAM, internal SRAM or external SRAM.

- Interfaces directly to a single-scan panel monochrome STN LCD
- Interfaces to a single-scan panel color STN LCD with minimal external glue logic
- Panel width size is programmable from 32 to 1024 pixels in 16-pixel increments
- Video frame buffer size programmable up to 128 KB
- Bits per pixel of 1, 2, or 4 bits

| Pin Mnemonic | I/O | Pin Description |
|--------------|-----|---------------------------------|
| CL1 | O | LCD line clock |
| CL2 | O | LCD pixel clock out |
| DD[3:0] | O | LCD serial display data bus |
| FRM | O | LCD frame synchronization pulse |
| M | O | LCD AC bias drive |

Table 8. LCD Interface Pin Assignments

64-Keypad Interface

Matrix keyboards and keypads can be easily read by the EP7309. A dedicated 8-bit column driver output generates strobes for each keyboard column signal. The pins of Port A, when configured as inputs, can be selectively OR'ed together to provide a keyboard interrupt that is capable of waking the system from a STANDBY or IDLE state.

- Column outputs can be individually set high with the remaining bits left at high-impedance
- Column outputs can be driven all-low, all-high, or all-high-impedance
- Keyboard interrupt driven by OR'ing together all Port A bits
- Keyboard interrupt can be used to wake up the system
- 8x8 keyboard matrix usable with no external logic, extra keys can be added with minimal glue logic

| Pin Mnemonic | I/O | Pin Description |
|--------------|-----|-------------------------------|
| COL[7:0] | O | Keyboard scanner column drive |

Table 9. Keypad Interface Pin Assignments

Interrupt Controller

When unexpected events arise during the execution of a program (i.e., interrupt or memory fault) an exception is usually generated. When these exceptions occur at the same time, a fixed priority system determines the order in which they are handled. The EP7309 interrupt controller has two interrupt types: interrupt request (IRQ) and fast interrupt request (FIQ). The interrupt controller has the ability to control interrupts from 22 different FIQ and IRQ sources.

- Supports 22 interrupts from a variety of sources (such as UARTs, SSI1, and key matrix.)
- Routes interrupt sources to the ARM720T's IRQ or FIQ (Fast IRQ) inputs
- Five dedicated off-chip interrupt lines operate as level sensitive interrupts

| Pin Mnemonic | I/O | Pin Description |
|----------------------|-----|-------------------------------|
| nEINT[2:1] | I | External interrupt |
| EINT[3] | I | External interrupt |
| nEXTFIQ | I | External Fast Interrupt input |
| nMEDCHG/nBROM (Note) | I | Media change interrupt input |

Table 10. Interrupt Controller Pin Assignments

Note: Pins are multiplexed. See [Table 18 on page 10](#) for more information.

Real-Time Clock

The EP7309 contains a 32-bit Real Time Clock (RTC) that can be written to and read from in the same manner as the timer counters. It also contains a 32-bit output match register which can be programmed to generate an interrupt.

- Driven by an external 32.768 kHz crystal oscillator

| Pin Mnemonic | Pin Description |
|--------------|-----------------------------------|
| RTCIN | Real-Time Clock Oscillator Input |
| RTCCOUT | Real-Time Clock Oscillator Output |
| VDDRTC | Real-Time Clock Oscillator Power |
| VSSRTC | Real-Time Clock Oscillator Ground |

Table 11. Real-Time Clock Pin Assignments

PLL and Clocking

- Processor and Peripheral Clocks operate from a single 3.6864 MHz crystal or external 13 MHz clock
- Programmable clock speeds allow the peripheral bus to run at 18 MHz when the processor is set to 18 MHz and at 36 MHz when the processor is set to 36, 49 or 74 MHz

| Pin Mnemonic | Pin Description |
|--------------|------------------------|
| MOSCIN | Main Oscillator Input |
| MOSCCOUT | Main Oscillator Output |
| VDDOSC | Main Oscillator Power |
| VSSOSC | Main Oscillator Ground |

Table 12. PLL and Clocking Pin Assignments

DC-to-DC converter interface (PWM)

- Provides two 96 kHz clock outputs with programmable duty ratio (from 1-in-16 to 15-in-16) that can be used to drive a positive or negative DC to DC converter

| Pin Mnemonic | I/O | Pin Description |
|--------------|-----|--------------------|
| DRIVE[1:0] | I/O | PWM drive output |
| FB[1:0] | I | PWM feedback input |

Table 13. DC-to-DC Converter Interface Pin Assignments

Timers

- Internal (RTC) timer
- Two internal 16-bit programmable hardware count-down timers

General Purpose Input/Output (GPIO)

- Three 8-bit and one 3-bit GPIO ports
- Supports scanning keyboard matrix

| Pin Mnemonic | I/O | Pin Description |
|-----------------------------|-----|-----------------|
| PA[7:0] | I/O | GPIO port A |
| PB[7:0] | I/O | GPIO port B |
| PD[0]/LEDFLSH (Note) | I/O | GPIO port D |
| PD[5:1] | I/O | GPIO port D |
| PD[7:6]/SDQM[1:0] (Note) | I/O | GPIO port D |
| PE[1:0]/BOOTSEL[1:0] (Note) | I/O | GPIO port E |
| PE[2]/CLKSEL (Note) | I/O | GPIO port E |

Table 14. General Purpose Input/Output Pin Assignments

Note: Pins are multiplexed. See [Table 18 on page 10](#) for more information.

Hardware debug Interface

- Full JTAG boundary scan and Embedded ICE[®] support

| Pin Mnemonic | I/O | Pin Description |
|--------------|-----|------------------------|
| TCLK | I | JTAG clock |
| TDI | I | JTAG data input |
| TDO | O | JTAG data output |
| nTRST | I | JTAG async reset input |
| TMS | I | JTAG mode select |

Table 15. Hardware Debug Interface Pin Assignments

LED Flasher

A dedicated LED flasher module can be used to generate a low frequency signal on Port D pin 0 for the purpose of blinking an LED without CPU intervention. The LED flasher feature is ideal as a visual annunciator in battery powered applications, such as a voice mail indicator on a portable phone or an appointment reminder on a PDA.

- Software adjustable flash period and duty cycle
- Operates from 32 kHz RTC clock
- Will continue to flash in IDLE and STANDBY states
- 4 mA drive current

| Pin Mnemonic | I/O | Pin Description |
|----------------------|-----|--------------------|
| PD[0]/LEDFLSH (Note) | O | LED flasher driver |

Table 16. LED Flasher Pin Assignments

Note: Pins are multiplexed. See [Table 18 on page 10](#) for more information.

Internal Boot ROM

The internal 128 byte Boot ROM facilitates download of saved code to the on-board SRAM/FLASH.

Packaging

The EP7309 is available in a 208-pin LQFP package, 256-ball PBGA package or a 204-ball TFBGA package.

Pin Multiplexing

The following table shows the pin multiplexing of the DAI, SSI2 and the CODEC. The selection between SSI2 and the CODEC is controlled by the SERSEL bit in SYSCON2. The choice between the SSI2, CODEC, and the DAI is controlled by the DAISEL bit in SYSCON3 (see the EP7309 User's Manual for more information).

| Pin Mnemonic | I/O | DAI | SSI2 | CODEC |
|--------------|-----|-------|---------|--------|
| SSICLK | I/O | SCLK | SSICLK | PCMCLK |
| SSITXDA | O | SDOUT | SSITXDA | PCMOUT |
| SSIRXDA | I | SDIN | SSIRXDA | PCMIN |

Table 17. DAI/SSI2/CODEC Pin Multiplexing

| Pin Mnemonic | I/O | DAI | SSI2 | CODEC |
|--------------|-----|---------|---------|---------|
| SSITXFR | I/O | LRCK | SSITXFR | PCMSYNC |
| SSIRXFR | I | MCLKIN | SSIRXFR | p/u |
| BUZ | O | MCLKOUT | | |

Table 17. DAI/SSI2/CODEC Pin Multiplexing

The following table shows the pins that have been multiplexed in the EP7309.

| Signal | Block | Signal | Block |
|---------|----------------------|--------------|----------------------|
| RUN | System Configuration | CLKEN | System Configuration |
| nMEDCHG | Interrupt Controller | nBROM | Boot ROM select |
| PD[0] | GPIO | LEDFLSH | LED Flasher |
| PE[1:0] | GPIO | BOOTSEL[1:0] | System Configuration |
| PE[2] | GPIO | CLKSEL | System Configuration |

Table 18. Pin Multiplexing

System Design

As shown in system block diagram, simply adding desired memory and peripherals to the highly integrated EP7309

completes a low-power system solution. All necessary interface logic is integrated on-chip.

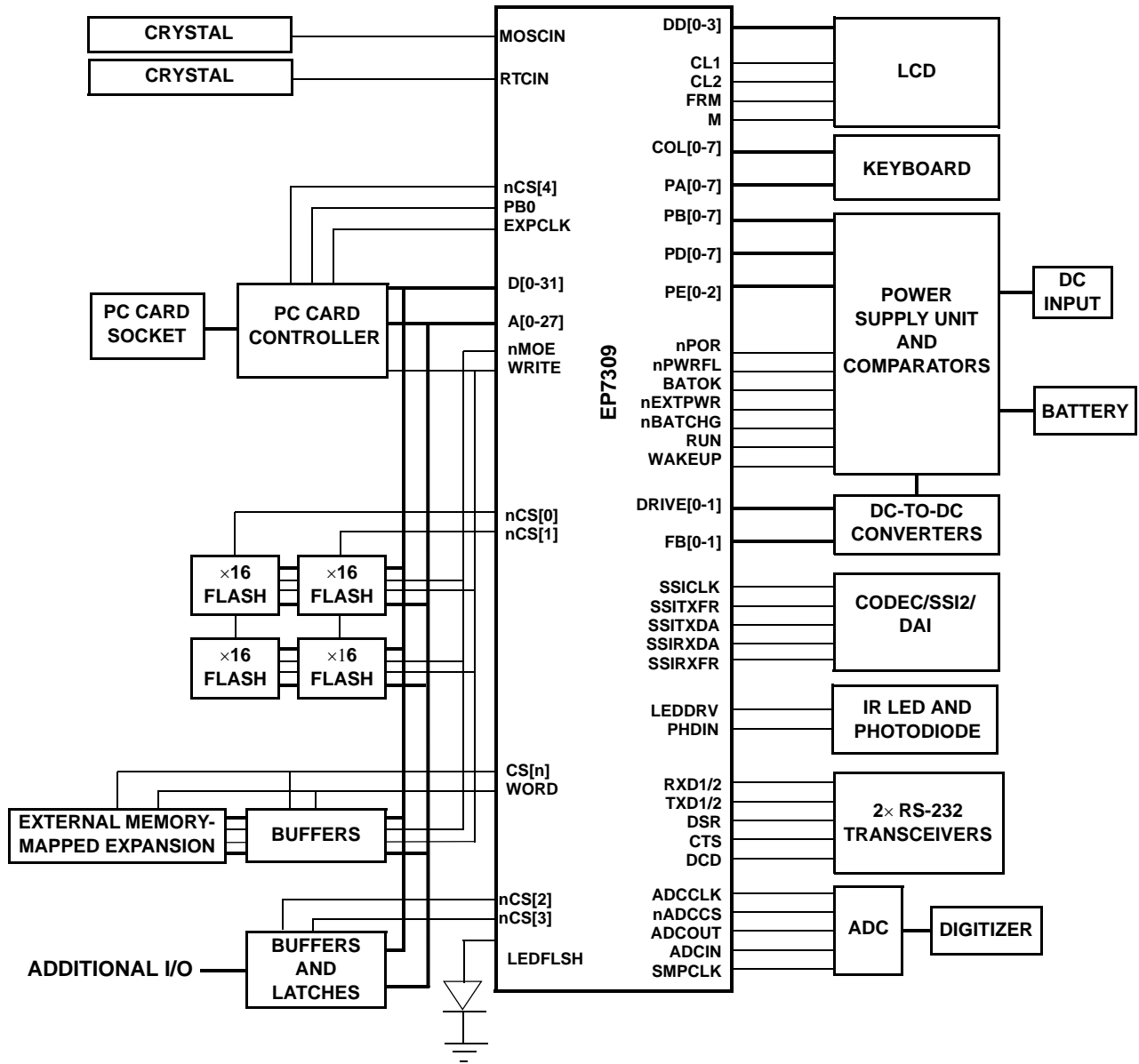


Figure 1. A Maximum EP7309 Based System

Note: A system can only use one of the following peripheral interfaces at any given time: SSI2, CODEC or DAI.

ELECTRICAL SPECIFICATIONS

Absolute Maximum Ratings

| | |
|--------------------------------------|--------------------------------|
| DC Core, PLL, and RTC Supply Voltage | 2.9 V |
| DC I/O Supply Voltage (Pad Ring) | 3.6 V |
| DC Pad Input Current | ±10 mA/pin; ±100 mA cumulative |
| Storage Temperature, No Power | -40°C to +125°C |

Recommended Operating Conditions

| | |
|--------------------------------------|---|
| DC core, PLL, and RTC Supply Voltage | 2.5 V ± 0.2 V |
| DC I/O Supply Voltage (Pad Ring) | 2.3 V - 3.5 V |
| DC Input / Output Voltage | O-I/O supply voltage |
| Operating Temperature | Extended -20°C to +70°C; Commercial 0°C to +70°C; Industrial -40°C to +85°C |

DC Characteristics

All characteristics are specified at $V_{DDCORE} = 2.5$ V, $V_{DDIO} = 3.3$ V and $V_{SS} = 0$ V over an operating temperature of 0°C to +70°C for all frequencies of operation. The current consumption figures have test conditions specified per parameter.”

| Symbol | Parameter | Min | Typ | Max | Unit | Conditions |
|--------|--|------------------------|-----|------------------------|------|---------------------------|
| VIH | CMOS input high voltage | $0.65 \times V_{DDIO}$ | - | $V_{DDIO} + 0.3$ | V | $V_{DDIO} = 2.5$ V |
| VIL | CMOS input low voltage | $V_{SS} - 0.3$ | - | $0.25 \times V_{DDIO}$ | V | $V_{DDIO} = 2.5$ V |
| VT+ | Schmitt trigger positive going threshold | - | - | 2.1 | V | |
| VT- | Schmitt trigger negative going threshold | 0.8 | - | - | V | |
| Vhst | Schmitt trigger hysteresis | 0.1 | - | 0.4 | V | VIL to VIH |
| VOH | CMOS output high voltage ^a | $V_{DD} - 0.2$ | - | - | V | IOH = 0.1 mA |
| | Output drive 1 ^a | 2.5 | - | - | V | IOH = 4 mA |
| | Output drive 2 ^a | 2.5 | - | - | V | IOH = 12 mA |
| VOL | CMOS output low voltage ^a | - | - | 0.3 | V | IOL = -0.1 mA |
| | Output drive 1 ^a | - | - | 0.5 | V | IOL = -4 mA |
| | Output drive 2 ^a | - | - | 0.5 | V | IOL = -12 mA |
| IIN | Input leakage current | - | - | 1.0 | µA | $V_{IN} = V_{DD}$ or GND |
| IOZ | Bidirectional 3-state leakage current ^{b c} | 25 | - | 100 | µA | $V_{OUT} = V_{DD}$ or GND |
| CIN | Input capacitance | 8 | - | 10.0 | pF | |
| COUT | Output capacitance | 8 | - | 10.0 | pF | |

| Symbol | Parameter | Min | Typ | Max | Unit | Conditions |
|---------------------------|--|--------|----------|-------------|---------|--|
| CI/O | Transceiver capacitance | 8 | - | 10.0 | pF | |
| $IDD_{STANDBY}$ @ 25 C | Standby current consumption ¹ Core, Osc, RTC @2.5 V I/O @ 3.3 V | - - | 77 41 | - - | μ A | Only nPOR, nPWRFAIL, nURESET, PE0, PE1, and RTS are driven, while all other float, $V_{IH} = V_{DD} \pm 0.1$ V, $V_{IL} = GND \pm 0.1$ V |
| $IDD_{STANDBY}$ @ 70 C | Standby current consumption ¹ Core, Osc, RTC @2.5 V I/O @ 3.3 V | - - | - - | 570 111 | μ A | Only nPOR, nPWRFAIL, nURESET, PE0, PE1, and RTS are driven, while all other float, $V_{IH} = V_{DD} \pm 0.1$ V, $V_{IL} = GND \pm 0.1$ V |
| $IDD_{STANDBY}$ @ 85 C | Standby current consumption ¹ Core, Osc, RTC @2.5 V I/O @ 3.3 V | - - | - - | 1693 163 | μ A | Only nPOR, nPWRFAIL, nURESET, PE0, PE1, and RTS are driven, while all other float, $V_{IH} = V_{DD} \pm 0.1$ V, $V_{IL} = GND \pm 0.1$ V |
| IDD_{idle} at 74 MHz | Idle current consumption ¹ Core, Osc, RTC @2.5 V I/O @ 3.3 V | - - | 6 10 | - - | mA | Both oscillators running, CPU static, Cache enabled, LCD disabled, $V_{IH} = V_{DD} \pm 0.1$ V, $V_{IL} = GND \pm 0.1$ V |
| $VDD_{STANDBY}$ | Standby supply voltage | 2.0 | - | - | V | Minimum standby voltage for state retention, internal SRAM cache, and RTC operation only |

- Refer to the strength column in the pin assignment tables for all package types.
- Assumes buffer has no pull-up or pull-down resistors.
- The leakage value given assumes that the pin is configured as an input pin but is not currently being driven.

Note: 1) Total power consumption = $IDD_{CORE} \times 2.5$ V + $IDD_{IO} \times 3.3$ V
2) A typical design will provide 3.3 V to the I/O supply (i.e., V_{DDIO}), and 2.5 V to the remaining logic. This is to allow the I/O to be compatible with 3.3 V powered external logic (i.e., 3.3 V SDRAMs).
2) Pull-up current = 50 μ A typical at $V_{DD} = 3.3$ V.

Timings

Timing Diagram Conventions

This data sheet contains timing diagrams. The following key explains the components used in these diagrams. Any variations are clearly labelled when they occur. Therefore, no additional meaning should be attached unless specifically stated.

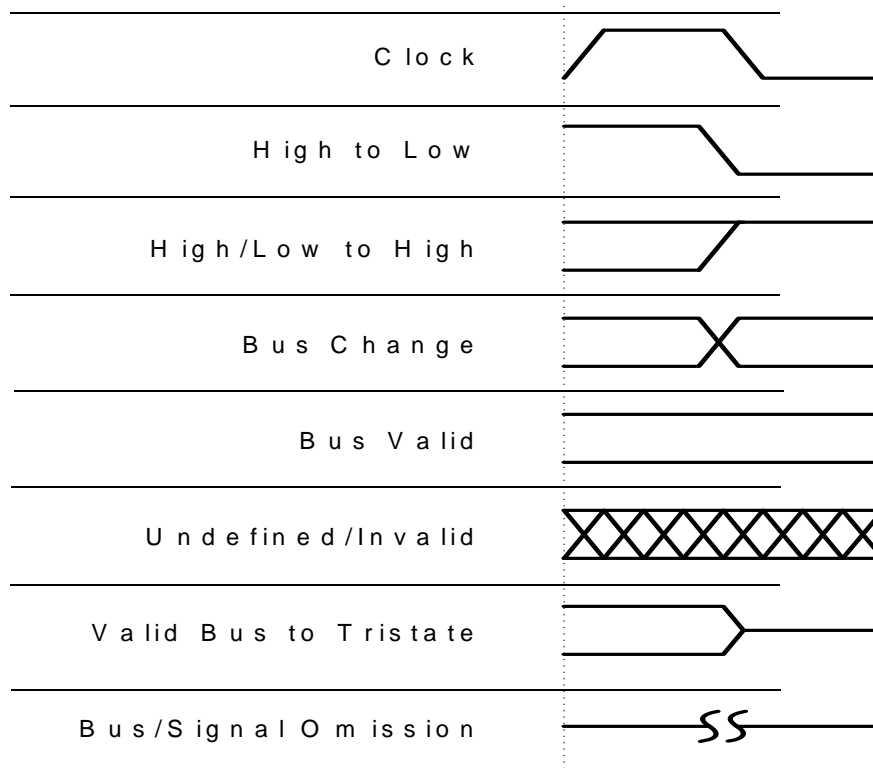


Figure 2. Legend for Timing Diagrams

Timing Conditions

Unless specified otherwise, the following conditions are true for all timing measurements. All characteristics are specified at $V_{DDIO} = 3.1 - 3.5 \text{ V}$ and $V_{SS} = 0 \text{ V}$ over an operating temperature of -40°C to $+85^{\circ}\text{C}$. Pin loadings is 50 pF . The timing values are referenced to $1/2 V_{DD}$.

Static Memory

Figure 3 through Figure 6 define the timings associated with all phases of the Static Memory. The following table contains the values for the timings of each of the Static Memory modes.

| Parameter | Symbol | Min | Typ | Max | Unit |
|---|------------|-----|-----|-----|------|
| EXPCLK rising edge to nCS assert delay time | t_{CSd} | 2 | 8 | 20 | ns |
| EXPCLK falling edge to nCS deassert hold time | t_{CSh} | 2 | 7 | 20 | ns |
| EXPCLK rising edge to A assert delay time | t_{Ad} | 4 | 9 | 16 | ns |
| EXPCLK falling edge to A deassert hold time | t_{Ah} | 3 | 10 | 19 | ns |
| EXPCLK rising edge to nMWE assert delay time | t_{MWd} | 3 | 6 | 10 | ns |
| EXPCLK rising edge to nMWE deassert hold time | t_{MWh} | 3 | 6 | 10 | ns |
| EXPCLK falling edge to nMOE assert delay time | t_{MOEd} | 3 | 7 | 10 | ns |
| EXPCLK falling edge to nMOE deassert hold time | t_{MOEh} | 2 | 7 | 10 | ns |
| EXPCLK falling edge to HALFWORD deassert delay time | t_{HWd} | 2 | 8 | 20 | ns |
| EXPCLK falling edge to WORD assert delay time | t_{WDd} | 2 | 8 | 16 | ns |
| EXPCLK rising edge to data valid delay time | t_{Dv} | 8 | 13 | 21 | ns |
| EXPCLK falling edge to data invalid delay time | t_{Dnv} | 6 | 15 | 30 | ns |
| Data setup to EXPCLK falling edge time | t_{Ds} | - | - | 1 | ns |
| EXPCLK falling edge to data hold time | t_{Dh} | - | - | 3 | ns |
| EXPCLK rising edge to WRITE assert delay time | t_{WRd} | 5 | 11 | 23 | ns |
| EXPREADY setup to EXPCLK falling edge time | t_{EXs} | - | - | 0 | ns |
| EXPCLK falling edge to EXPREADY hold time | t_{EXh} | - | - | 0 | ns |

Static Memory Single Read Cycle

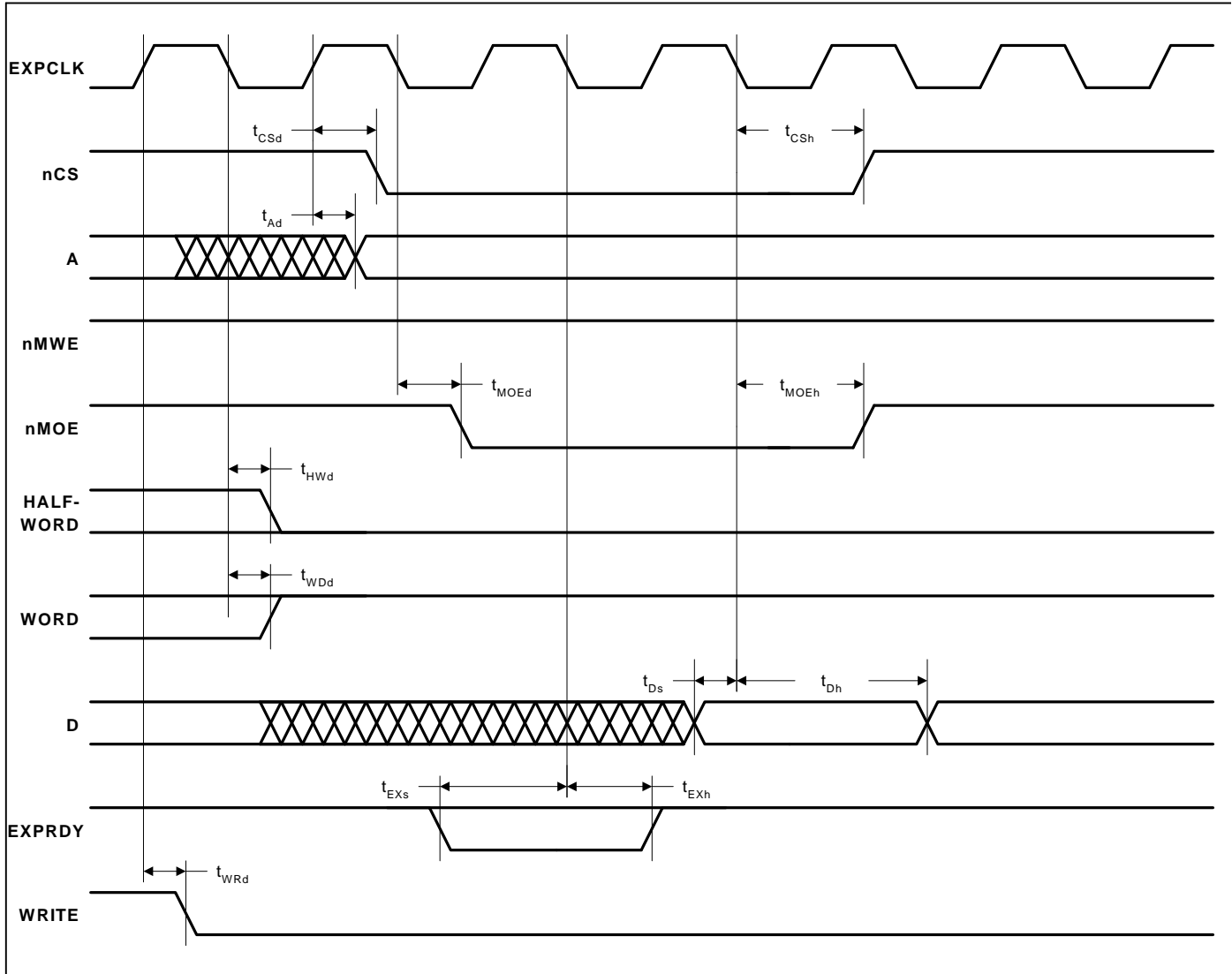
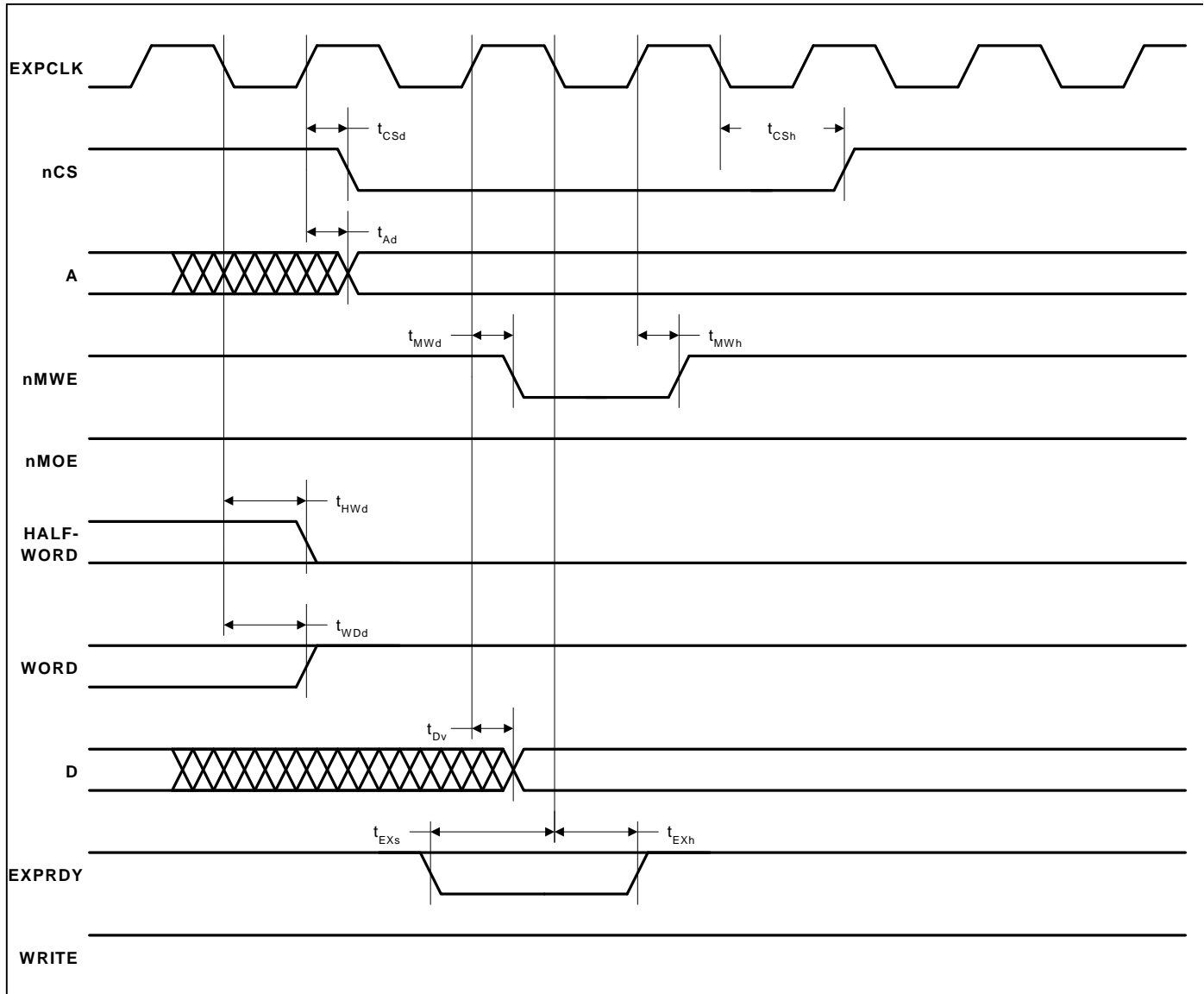


Figure 3. Static Memory Single Read Cycle Timing Measurement

Note: 1. The cycle time can be extended by integer multiples of the clock period (22 ns at 45 MHz, 27 ns at 36 MHz, 54 ns at 18.432 MHz, and 77 ns at 13 MHz), by either driving EXPRDY low and/or by programming a number of wait states. EXPRDY is sampled on the falling edge of EXPCLK before the data transfer. If low at this point, the transfer is delayed by one clock period where EXPRDY is sampled again. EXPCLK need not be referenced when driving EXPRDY, but is shown for clarity.
2. Address, Halfword, Word, and Write hold state until next cycle.

Static Memory Single Write Cycle

Figure 4. Static Memory Single Write Cycle Timing Measurement

- Note:
1. The cycle time can be extended by integer multiples of the clock period (22 ns at 45 MHz, 27 ns at 36 MHz, 54 ns at 18.432 MHz, and 77 ns at 13 MHz), by either driving EXPRDY low and/or by programming a number of wait states. EXPRDY is sampled on the falling edge of EXPCLK before the data transfer. If low at this point, the transfer is delayed by one clock period where EXPRDY is sampled again. EXPCLK need not be referenced when driving EXPRDY, but is shown for clarity.
 2. Zero wait states for sequential writes is not permitted for memory devices which use nMWE pin, as this cannot be driven with valid timing under zero wait state conditions.
 3. Address, Data, Halfword, Word, and Write hold state until next cycle.

Static Memory Burst Read Cycle

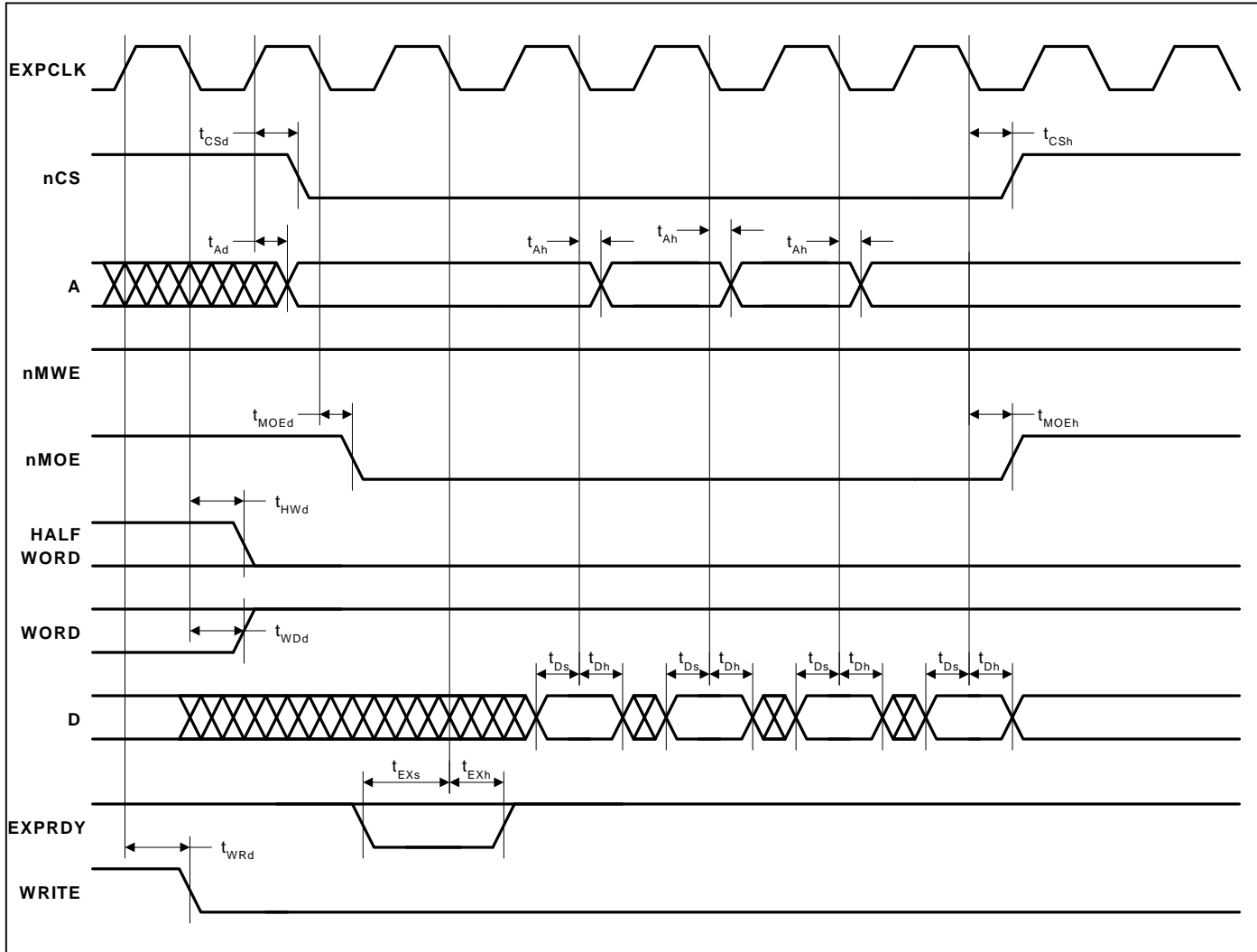
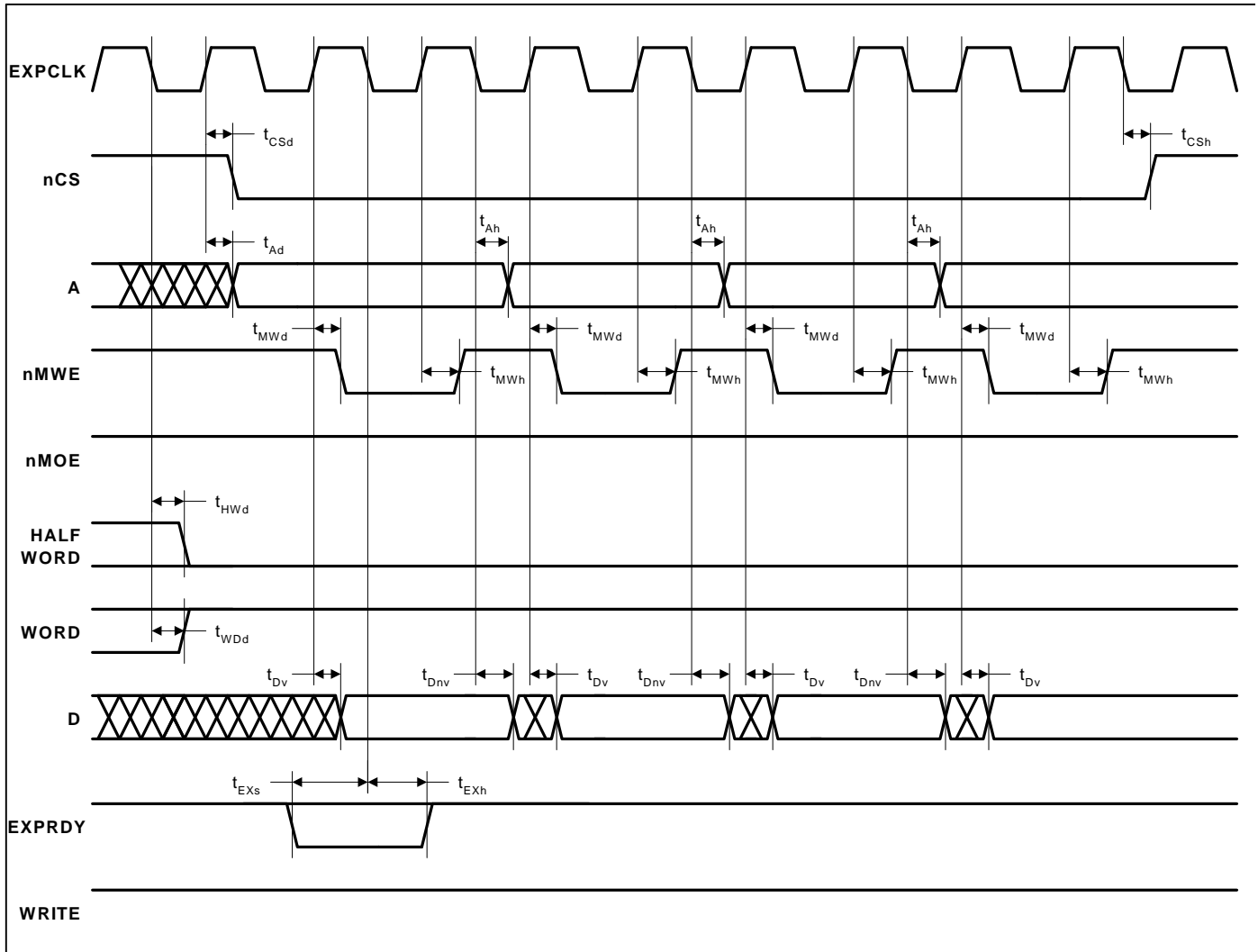


Figure 5. Static Memory Burst Read Cycle Timing Measurement

- Note:
1. Four cycles are shown in the above diagram (minimum wait states, 1-0-0-0). This is the maximum number of consecutive cycles that can be driven. The number of consecutive cycles can be programmed from 2 to 4, inclusively.
 2. The cycle time can be extended by integer multiples of the clock period (22 ns at 45 MHz, 27 ns at 36 MHz, 54 ns at 18.432 MHz, and 77 ns at 13 MHz), by either driving EXPRDY low and/or by programming a number of wait states. EXPRDY is sampled on the falling edge of EXPCLK before the data transfer. If low at this point, the transfer is delayed by one clock period where EXPRDY is sampled again. EXPCLK need not be referenced when driving EXPRDY, but is shown for clarity.
 3. Consecutive reads with sequential access enabled are identical except that the sequential access wait state field is used to determine the number of wait states, and no idle cycles are inserted between successive non-sequential ROM/expansion cycles. This improves performance so the SQAEN bit should always be set where possible.
 4. Address, Halfword, Word, and Write hold state until next cycle.

Static Memory Burst Write Cycle

Figure 6. Static Memory Burst Write Cycle Timing Measurement

- Note:
- Four cycles are shown in the above diagram (minimum wait states, 1-1-1-1). This is the maximum number of consecutive cycles that can be driven. The number of consecutive cycles can be programmed from 2 to 4, inclusively.
 - The cycle time can be extended by integer multiples of the clock period (22 ns at 45 MHz, 27 ns at 36 MHz, 54 ns at 18.432 MHz, and 77 ns at 13 MHz), by either driving EXPRDY low and/or by programming a number of wait states. EXPRDY is sampled on the falling edge of EXPCLK before the data transfer. If low at this point, the transfer is delayed by one clock period where EXPRDY is sampled again. EXPCLK need not be referenced when driving EXPRDY, but is shown for clarity.
 - Zero wait states for sequential writes is not permitted for memory devices which use nMWE pin, as this cannot be driven with valid timing under zero wait state conditions.
 - Address, Data, Halfword, Word, and Write hold state until next cycle.

SSI1 Interface

| Parameter | Symbol | Min | Max | Unit |
|--|-----------|-----|-----|------|
| ADCCLK falling edge to nADCCSS deassert delay time | t_{Cd} | 9 | 10 | ms |
| ADCIN data setup to ADCCLK rising edge time | t_{INs} | - | 15 | ns |
| ADCIN data hold from ADCCLK rising edge time | t_{INh} | - | 14 | ns |
| ADCCLK falling edge to data valid delay time | t_{Ovd} | -7 | 13 | ns |
| ADCCLK falling edge to data invalid delay time | t_{Oid} | -2 | 3 | ns |

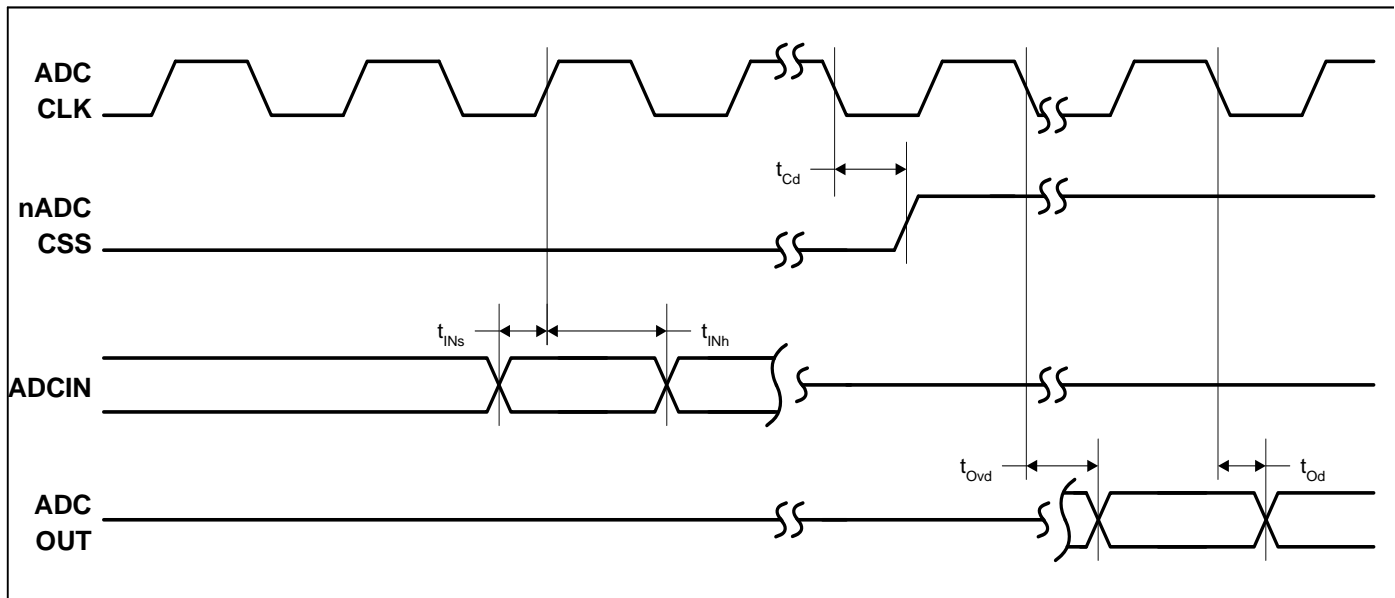


Figure 7. SSI1 Interface Timing Measurement

SSI2 Interface

| Parameter | Symbol | Min | Max | Unit |
|---|-----------------|-----|------|------|
| SSICLK period (slave mode) | t_{clk_per} | 185 | 2050 | ns |
| SSICLK high time | t_{clk_high} | 925 | 1025 | ns |
| SSICLK low time | t_{clk_low} | 925 | 1025 | ns |
| SSICLK rise/fall time | t_{clkrf} | 3 | 18 | ns |
| SSICLK rising edge to RX and/or TX frame sync high time | t_{FRd} | - | 3 | ns |
| SSICLK rising edge to RX and/or TX frame sync low time | t_{FRa} | - | 8 | ns |
| SSIRXFR and/or SSITXFR period | t_{FR_per} | 960 | 990 | ns |
| SSIRXDA setup to SSICLK falling edge time | t_{RXs} | 3 | 7 | ns |
| SSIRXDA hold from SSICLK falling edge time | t_{RXh} | 3 | 7 | ns |
| SSICLK rising edge to SSITXDA data valid delay time | t_{TXd} | - | 2 | ns |
| SSITXDA valid time | t_{TXv} | 960 | 990 | ns |

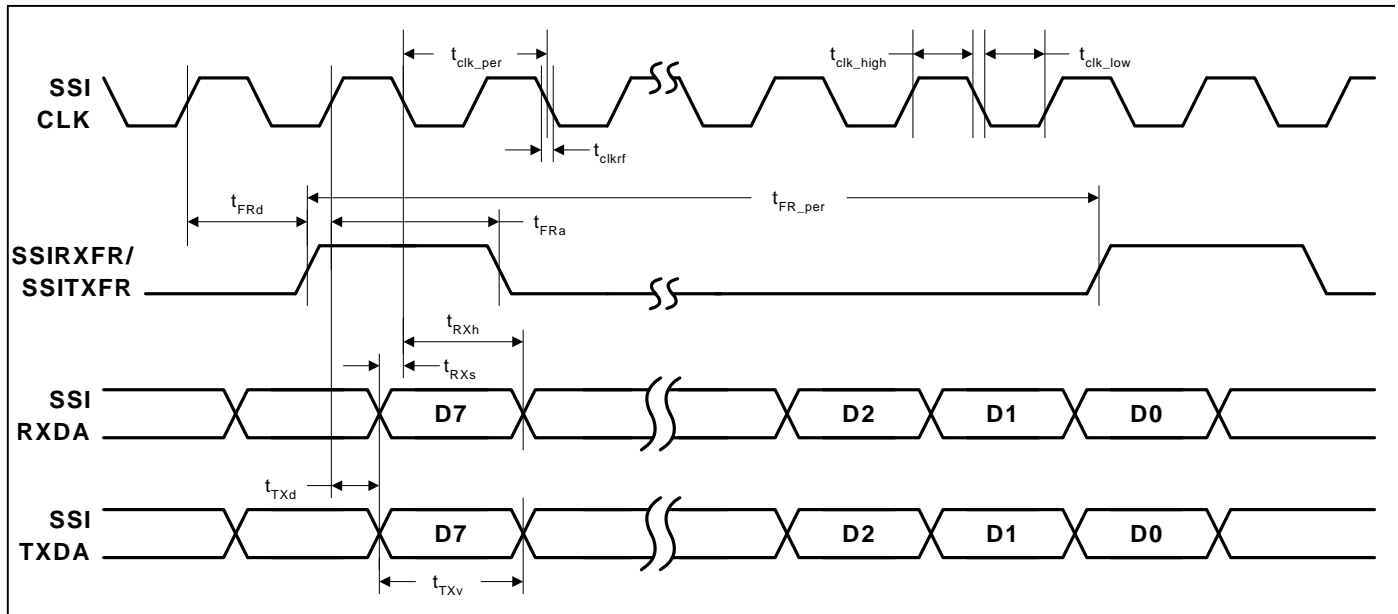


Figure 8. SSI2 Interface Timing Measurement

LCD Interface

| Parameter | Symbol | Min | Max | Unit |
|---|------------|------|--------|------|
| CL[2] falling to CL[1] rising delay time | t_{CL1d} | - 10 | 25 | ns |
| CL[1] falling to CL[2] rising delay time | t_{CL2d} | 80 | 3,475 | ns |
| CL[1] falling to FRM transition time | t_{FRMd} | 300 | 10,425 | ns |
| CL[1] falling to M transition time | t_{Md} | - 10 | 20 | ns |
| CL[2] rising to DD (display data) transition time | t_{DDd} | - 10 | 20 | ns |

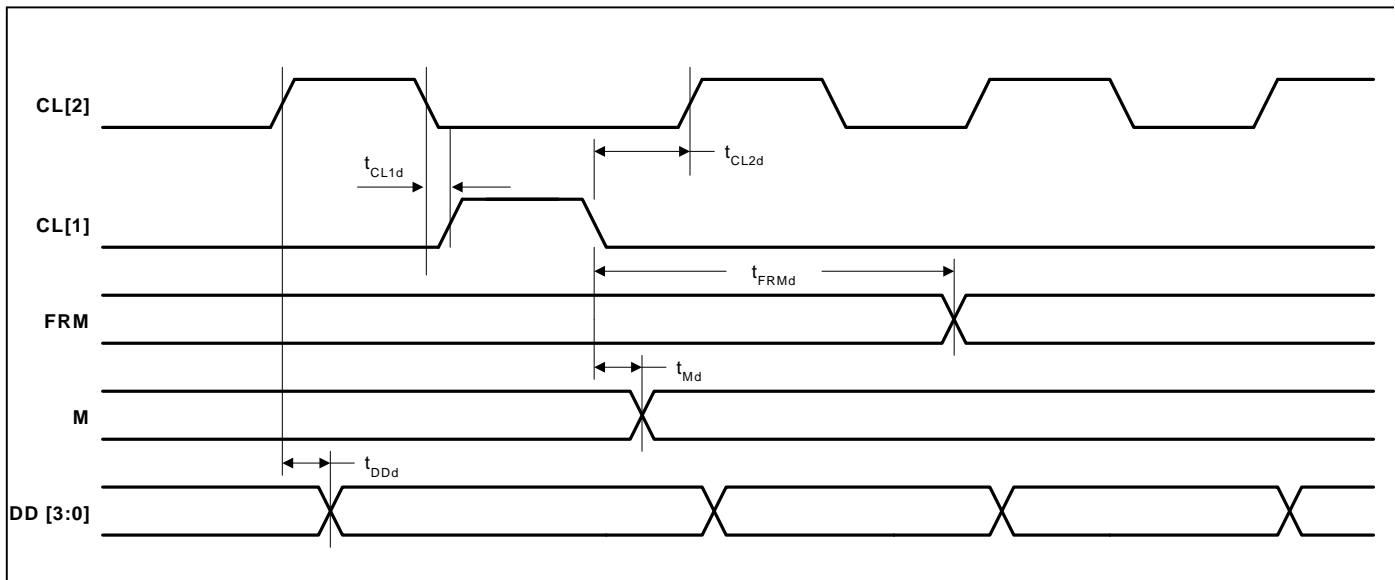


Figure 9. LCD Controller Timing Measurement

JTAG Interface

| Parameter | Symbol | Min | Max | Units |
|--|-----------------|-----|-----|-------|
| TCK clock period | t_{clk_per} | 2 | - | ns |
| TCK clock high time | t_{clk_high} | 1 | - | ns |
| TCK clock low time | t_{clk_low} | 1 | - | ns |
| JTAG port setup time | t_{JP_s} | - | 0 | ns |
| JTAG port hold time | t_{JP_h} | - | 3 | ns |
| JTAG port clock to output | $t_{JP_{co}}$ | - | 10 | ns |
| JTAG port high impedance to valid output | $t_{JP_{zx}}$ | - | 12 | ns |
| JTAG port valid output to high impedance | $t_{JP_{xz}}$ | - | 19 | ns |

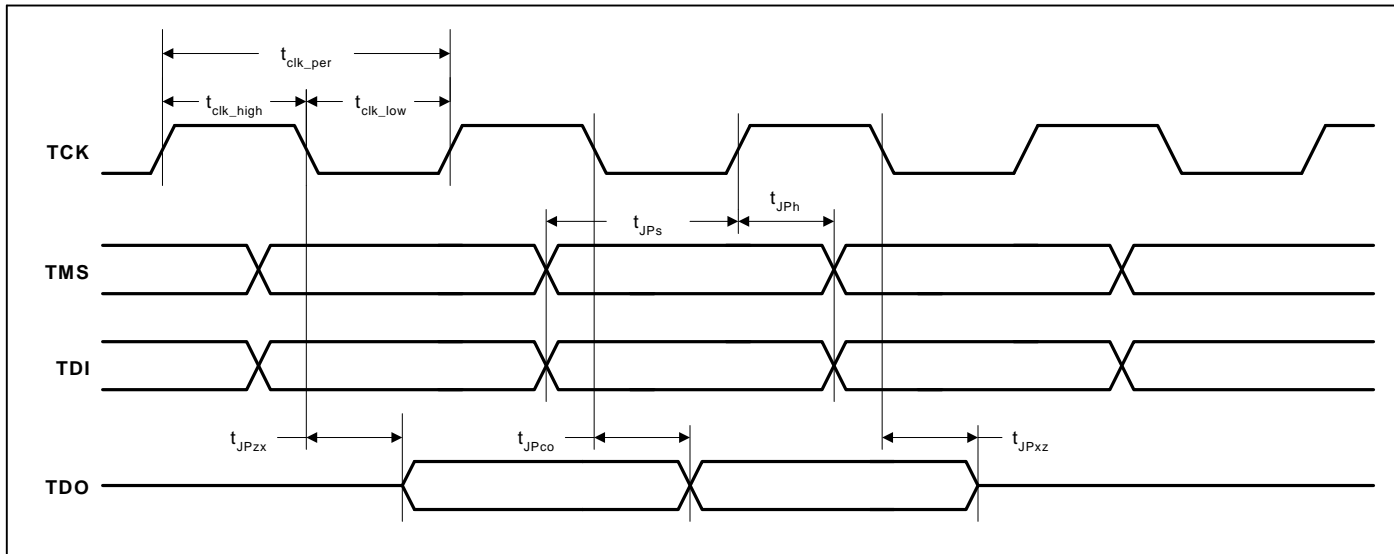


Figure 10. JTAG Timing Measurement

Packages

208-Pin LQFP Package Characteristics

208-Pin LQFP Package Specifications

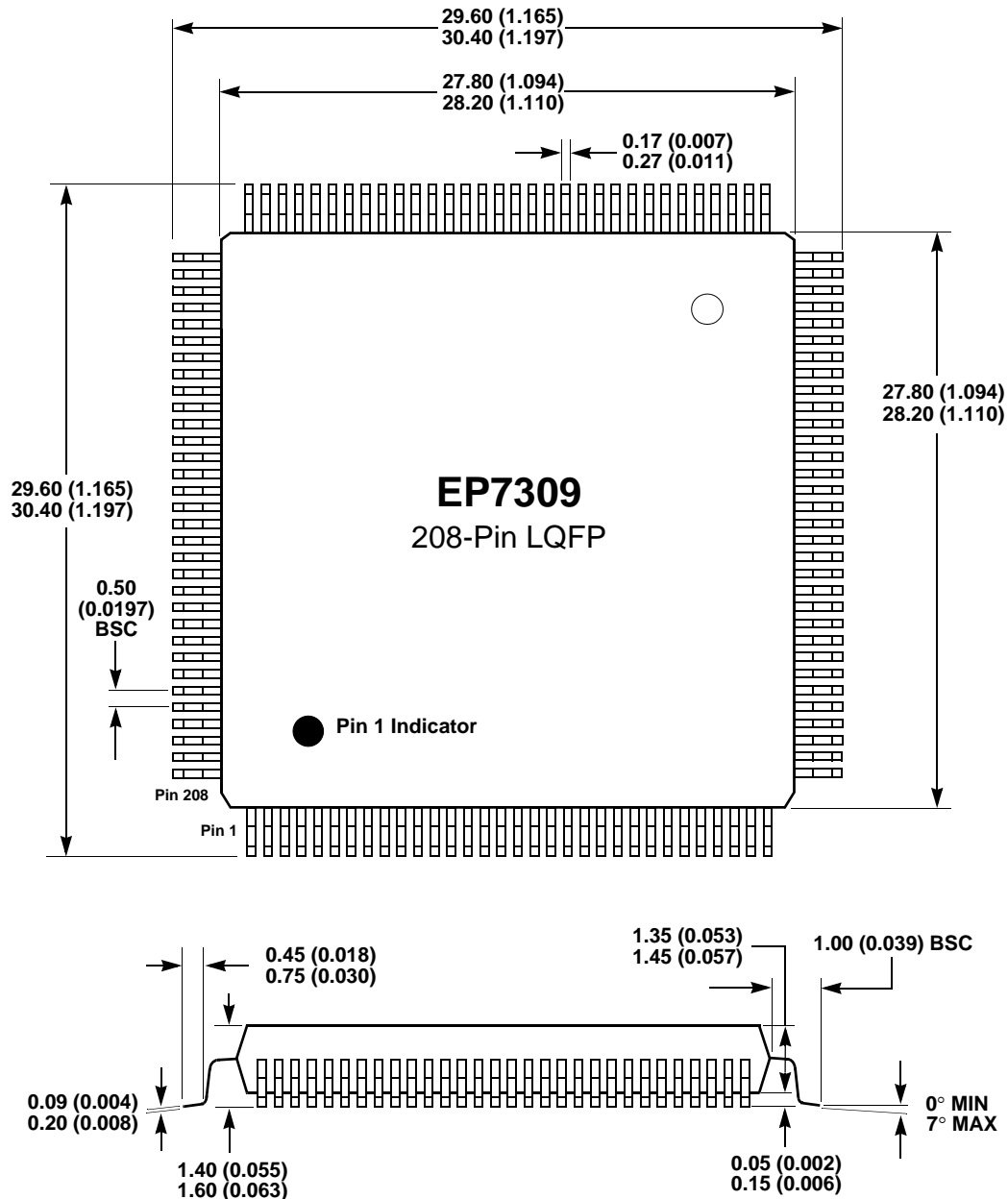


Figure 11. 208-Pin LQFP Package Outline Drawing

- Note:
- 1) Dimensions are in millimeters (inches), and controlling dimension is millimeter.
 - 2) Drawing above does not reflect exact package pin count.
 - 3) Before beginning any new design with this device, please contact Cirrus Logic for the latest package information.
 - 4) For pin locations, please see [Figure 12](#). For pin descriptions see the EP7309 User's Manual.

208-Pin LQFP Pin Diagram

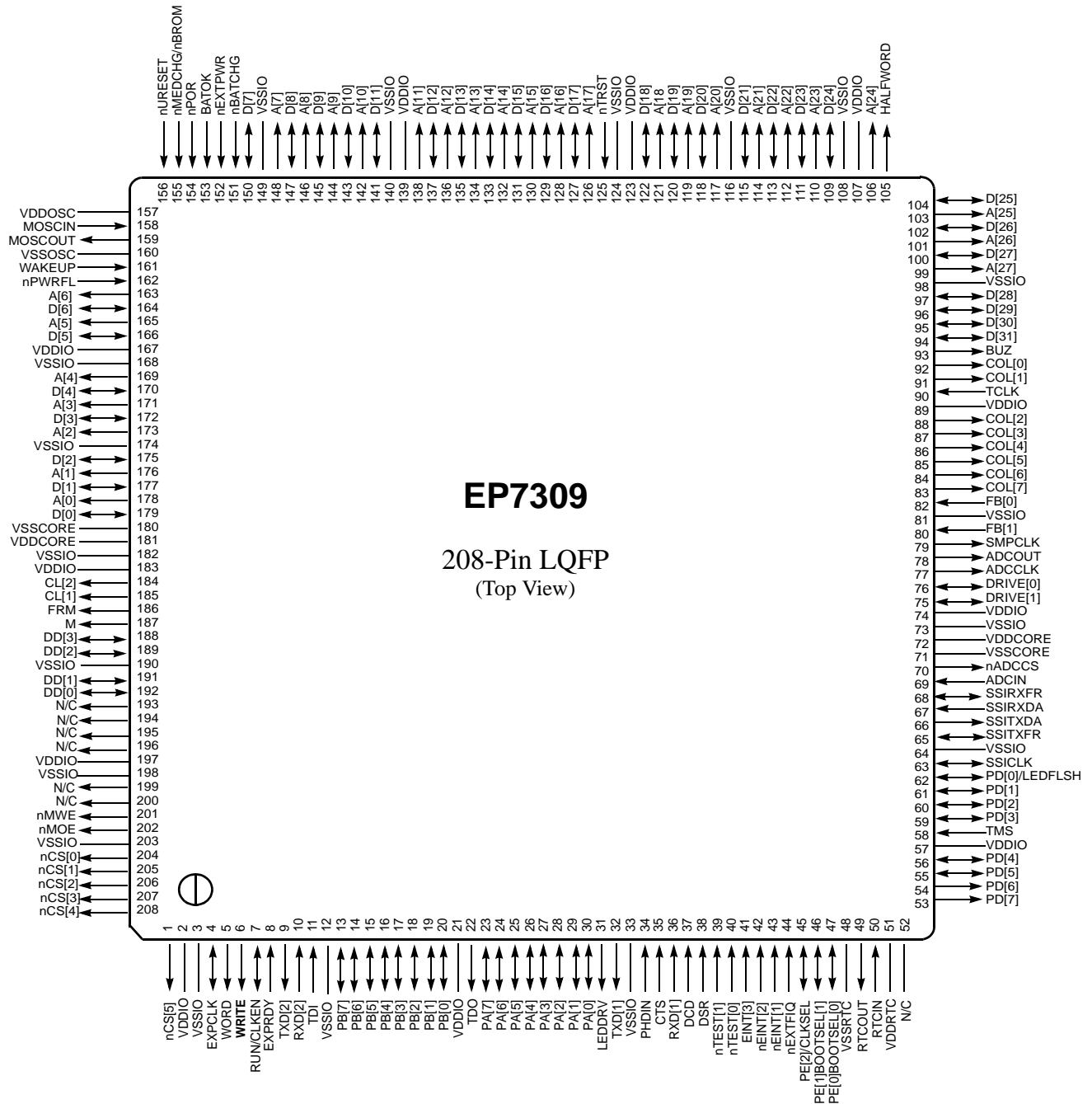


Figure 12. 208-Pin LQFP (Low Profile Quad Flat Pack) Pin Diagram

- Note: 1. N/C should not be grounded but left as no connects.
2. Pin differences between the EP7212 and the EP7309 are bolded.

208-Pin LQFP Numeric Pin Listing

Table 19. 208-Pin LQFP Numeric Pin Listing

| Pin No. | Signal | Type | Strength | Reset State |
|---------|-------------|---------|-----------|-------------|
| 1 | nCS[5] | O | 1 | High |
| 2 | VDDIO | Pad Pwr | | |
| 3 | VSSIO | Pad Gnd | | |
| 4 | EXPCLK | I/O | 1 | |
| 5 | WORD | Out | 1 | Low |
| 6 | WRITE | Out | 1 | Low |
| 7 | RUN/CLKEN | O | 1 | Low |
| 8 | EXPRDY | I | 1 | |
| 9 | TXD[2] | O | 1 | High |
| 10 | RXD[2] | I | | |
| 11 | TDI | I | with p/u* | |
| 12 | VSSIO | Pad Gnd | | |
| 13 | PB[7] | I/O | 1 | Input |
| 14 | PB[6] | I/O | 1 | Input |
| 15 | PB[5] | I/O | 1 | Input |
| 16 | PB[4] | I/O | 1 | Input |
| 17 | PB[3] | I/O | 1 | Input |
| 18 | PB[2] | I/O | 1 | Input |
| 19 | PB[1]/PRDY2 | I/O | 1 | Input |
| 20 | PB[0]/PRDY1 | I/O | 1 | Input |
| 21 | VDDIO | Pad Pwr | | |
| 22 | TDO | O | 1 | Three state |
| 23 | PA[7] | I/O | 1 | Input |
| 24 | PA[6] | I/O | 1 | Input |
| 25 | PA[5] | I/O | 1 | Input |
| 26 | PA[4] | I/O | 1 | Input |
| 27 | PA[3] | I/O | 1 | Input |
| 28 | PA[2] | I/O | 1 | Input |
| 29 | PA[1] | I/O | 1 | Input |
| 30 | PA[0] | I/O | 1 | Input |
| 31 | LEDDRV | O | 1 | Low |
| 32 | TXD[1] | O | 1 | High |
| 33 | VSSIO | Pad Gnd | 1 | High |
| 34 | PHDIN | I | | |
| 35 | CTS | I | | |
| 36 | RXD[1] | I | | |

Table 19. 208-Pin LQFP Numeric Pin Listing (Continued)

| Pin No. | Signal | Type | Strength | Reset State |
|---------|----------------------|-----------|-----------|-------------|
| 37 | DCD | I | | |
| 38 | DSR | I | | |
| 39 | nTEST[1] | I | With p/u* | |
| 40 | nTEST[0] | I | With p/u* | |
| 41 | EINT[3] | I | | |
| 42 | nEINT[2] | I | | |
| 43 | nEINT[1] | I | | |
| 44 | nEXTFIQ | I | | |
| 45 | PE[2]/CLKSEL | I/O | 1 | Input |
| 46 | PE[1]/ BOOTSEL[1] | I/O | 1 | Input |
| 47 | PE[0]/ BOOTSEL[0] | I/O | 1 | Input |
| 48 | VSSRTC | RTC Gnd | | |
| 49 | RTCCOUT | O | | |
| 50 | RTCCIN | I | | |
| 51 | VDDRTC | RTC power | | |
| 52 | N/C | | | |
| 53 | PD[7] | I/O | 1 | Low |
| 54 | PD[6] | I/O | 1 | Low |
| 55 | PD[5] | I/O | 1 | Low |
| 56 | PD[4] | I/O | 1 | Low |
| 57 | VDDIO | Pad Pwr | | |
| 58 | TMS | I | with p/u* | |
| 59 | PD[3] | I/O | 1 | Low |
| 60 | PD[2] | I/O | 1 | Low |
| 61 | PD[1] | I/O | 1 | Low |
| 62 | PD[0]/LEDFLSH | I/O | 1 | Low |
| 63 | SSICLK | I/O | 1 | Input |
| 64 | VSSIO | Pad Gnd | | |
| 65 | SSITXFR | I/O | 1 | Low |
| 66 | SSITXDA | O | 1 | Low |
| 67 | SSIRXDA | I | | |
| 68 | SSIRXFR | I/O | | Input |
| 69 | ADCIN | I | | |
| 70 | nADCCS | O | 1 | High |
| 71 | VSSCORE | Core Gnd | | |
| 72 | VDDCORE | Core Pwr | | |

Table 19. 208-Pin LQFP Numeric Pin Listing (Continued)

| Pin No. | Signal | Type | Strength | Reset State |
|---------|----------|---------|----------|-------------|
| 73 | VSSIO | Pad Gnd | | |
| 74 | VDDIO | Pad Pwr | | |
| 75 | DRIVE[1] | I/O | 2 | High / Low |
| 76 | DRIVE[0] | I/O | 2 | High / Low |
| 77 | ADCCLK | O | 1 | Low |
| 78 | ADCOUT | O | 1 | Low |
| 79 | SMPCLK | O | 1 | Low |
| 80 | FB[1] | I | | |
| 81 | VSSIO | Pad Gnd | | |
| 82 | FB[0] | I | | |
| 83 | COL[7] | O | 1 | High |
| 84 | COL[6] | O | 1 | High |
| 85 | COL[5] | O | 1 | High |
| 86 | COL[4] | O | 1 | High |
| 87 | COL[3] | O | 1 | High |
| 88 | COL[2] | O | 1 | High |
| 89 | VDDIO | Pad Pwr | | |
| 90 | TCLK | I | | |
| 91 | COL[1] | O | 1 | High |
| 92 | COL[0] | O | 1 | High |
| 93 | BUZ | O | 1 | Low |
| 94 | D[31] | I/O | 1 | Low |
| 95 | D[30] | I/O | 1 | Low |
| 96 | D[29] | I/O | 1 | Low |
| 97 | D[28] | I/O | 1 | Low |
| 98 | VSSIO | Pad Gnd | | |
| 99 | A[27] | O | 2 | Low |
| 100 | D[27] | I/O | 1 | Low |
| 101 | A[26] | O | 2 | Low |
| 102 | D[26] | I/O | 1 | Low |
| 103 | A[25] | O | 2 | Low |
| 104 | D[25] | I/O | 1 | Low |
| 105 | HALFWORD | O | 1 | Low |
| 106 | A[24] | O | 1 | Low |
| 107 | VDDIO | Pad Pwr | | — |
| 108 | VSSIO | Pad Gnd | | — |
| 109 | D[24] | I/O | 1 | Low |

Table 19. 208-Pin LQFP Numeric Pin Listing (Continued)

| Pin No. | Signal | Type | Strength | Reset State |
|---------|--------|---------|----------|-------------|
| 110 | A[23] | O | 1 | Low |
| 111 | D[23] | I/O | 1 | Low |
| 112 | A[22] | O | 1 | Low |
| 113 | D[22] | I/O | 1 | Low |
| 114 | A[21] | O | 1 | Low |
| 115 | D[21] | I/O | 1 | Low |
| 116 | VSSIO | Pad Gnd | | |
| 117 | A[20] | O | 1 | Low |
| 118 | D[20] | I/O | 1 | Low |
| 119 | A[19] | O | 1 | Low |
| 120 | D[19] | I/O | 1 | Low |
| 121 | A[18] | O | 1 | Low |
| 122 | D[18] | I/O | 1 | Low |
| 123 | VDDIO | Pad Pwr | | |
| 124 | VSSIO | Pad Gnd | | |
| 125 | nTRST | I | | |
| 126 | A[17] | O | 1 | Low |
| 127 | D[17] | I/O | 1 | Low |
| 128 | A[16] | O | 1 | Low |
| 129 | D[16] | I/O | 1 | Low |
| 130 | A[15] | O | 1 | Low |
| 131 | D[15] | I/O | 1 | Low |
| 132 | A[14] | O | 1 | Low |
| 133 | D[14] | I/O | 1 | Low |
| 134 | A[13] | O | 1 | Low |
| 135 | D[13] | I/O | 1 | Low |
| 136 | A[12] | O | 1 | Low |
| 137 | D[12] | I/O | 1 | Low |
| 138 | A[11] | O | 1 | Low |
| 139 | VDDIO | Pad Pwr | | |
| 140 | VSSIO | Pad Gnd | | |
| 141 | D[11] | I/O | 1 | Low |
| 142 | A[10] | O | 1 | Low |
| 143 | D[10] | I/O | 1 | Low |
| 144 | A[9] | O | 1 | Low |
| 145 | D[9] | I/O | 1 | Low |
| 146 | A[8] | O | 1 | Low |
| 147 | D[8] | I/O | 1 | Low |

Table 19. 208-Pin LQFP Numeric Pin Listing (Continued)

| Pin No. | Signal | Type | Strength | Reset State |
|---------|-------------------|----------|----------|-------------|
| 148 | A[7] | O | 1 | Low |
| 149 | VSSIO | Pad Gnd | | |
| 150 | D[7] | I/O | 1 | Low |
| 151 | nBATCHG | I | | |
| 152 | nEXTPWR | I | | |
| 153 | BATOK | I | | |
| 154 | nPOR | I | Schmitt | |
| 155 | nMEDCHG/ nBROM | I | | |
| 156 | nURESET | I | Schmitt | |
| 157 | VDDOSC | Osc Pwr | | |
| 158 | MOSCIN | Osc | | |
| 159 | MOSCOU | Osc | | |
| 160 | VSSOSC | Osc Gnd | | |
| 161 | WAKEUP | I | Schmitt | |
| 162 | nPWRFL | I | | |
| 163 | A[6] | O | 1 | Low |
| 164 | D[6] | I/O | 1 | Low |
| 165 | A[5] | Out | 1 | Low |
| 166 | D[5] | I/O | 1 | Low |
| 167 | VDDIO | Pad Pwr | | |
| 168 | VSSIO | Pad Gnd | | |
| 169 | A[4] | O | 1 | Low |
| 170 | D[4] | I/O | 1 | Low |
| 171 | A[3] | O | 2 | Low |
| 172 | D[3] | I/O | 1 | Low |
| 173 | A[2] | O | 2 | Low |
| 174 | VSSIO | Pad Gnd | | |
| 175 | D[2] | I/O | 1 | Low |
| 176 | A[1] | O | 2 | Low |
| 177 | D[1] | I/O | 1 | Low |
| 178 | A[0] | O | 2 | Low |
| 179 | D[0] | I/O | 1 | Low |
| 180 | VSS CORE | Core Gnd | | |
| 181 | VDD CORE | Core Pwr | | |
| 182 | VSSIO | Pad Gnd | | |
| 183 | VDDIO | Pad Pwr | | |
| 184 | CL[2] | O | 1 | Low |
| 185 | CL[1] | O | 1 | Low |

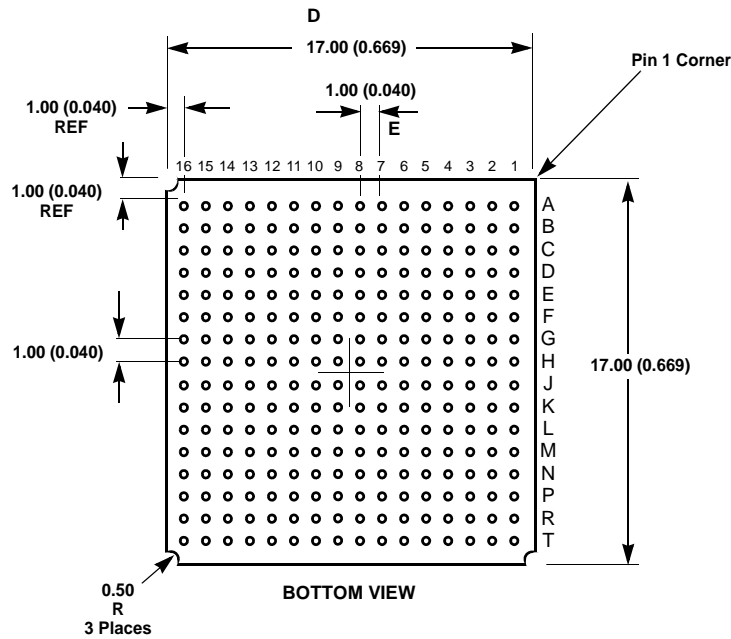
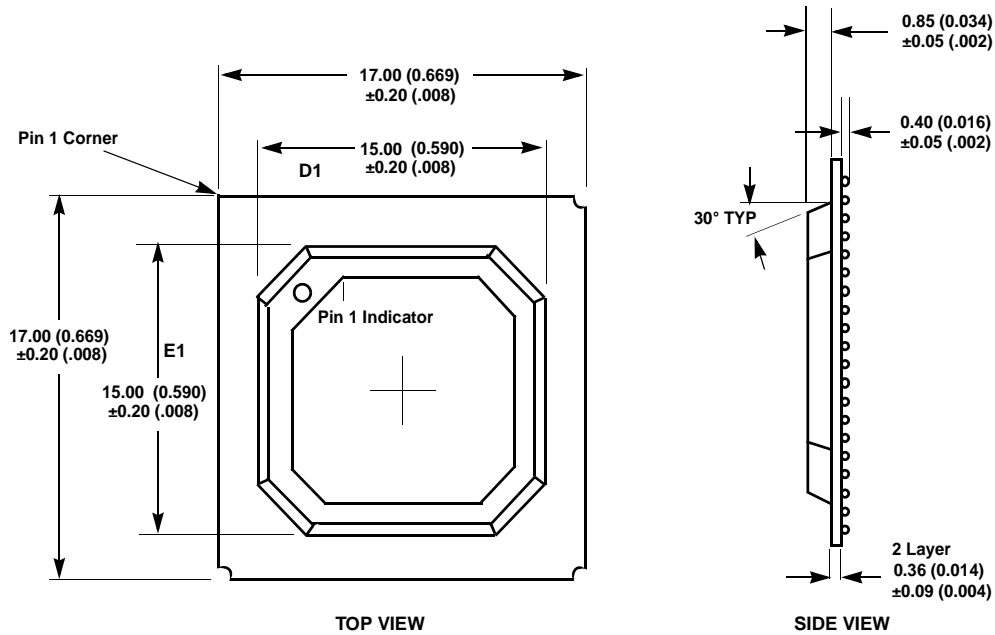
Table 19. 208-Pin LQFP Numeric Pin Listing (Continued)

| Pin No. | Signal | Type | Strength | Reset State |
|---------|--------|---------|----------|-------------|
| 186 | FRM | O | 1 | Low |
| 187 | M | O | 1 | Low |
| 188 | DD[3] | I/O | 1 | Low |
| 189 | DD[2] | I/O | 1 | Low |
| 190 | VSSIO | Pad Gnd | | |
| 191 | DD[1] | I/O | 1 | Low |
| 192 | DD[0] | I/O | 1 | Low |
| 193 | N/C | O | 1 | High |
| 194 | N/C | O | 1 | High |
| 195 | N/C | I/O | 2 | Low |
| 196 | N/C | I/O | 2 | Low |
| 197 | VDDIO | Pad Pwr | | |
| 198 | VSSIO | Pad Gnd | | |
| 199 | N/C | I/O | 2 | Low |
| 200 | N/C | I/O | 2 | Low |
| 201 | nMWE | O | 1 | High |
| 202 | nMOE | O | 1 | High |
| 203 | VSSIO | Pad Gnd | | |
| 204 | nCS[0] | O | 1 | High |
| 205 | nCS[1] | O | 1 | High |
| 206 | nCS[2] | O | 1 | High |
| 207 | nCS[3] | O | 1 | High |
| 208 | nCS[4] | O | 1 | High |

*With p/u' means with internal pull-up on the pin.

256-Ball PBGA Package Characteristics

256-Ball PBGA Package Specifications



JEDEC #: MO-151
 Ball Diameter: 0.50 mm ± 0.10 mm
 17 × 17 × 1.61 mm body

Figure 13. 256-Ball PBGA Package

- Note: 1) For pin locations see [Table 20](#).
 2) Dimensions are in millimeters (inches), and controlling dimension is millimeter
 3) Before beginning any new EP7309 design, contact Cirrus Logic for the latest package information.

256-Ball PBGA Pinout (Top View)

| | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | 10 | 11 | 12 | 13 | 14 | 15 | 16 | |
|---|----------|----------------------|--------|----------------------|------------------|---------|-------------------|----------|---------|--------|--------|--------|-------------------|--------|--------|---------|---|
| A | VDDIO | nCS[4] | nCS[1] | N/C | N/C | DD[1] | M | VDDIO | D[0] | D[2] | A[3] | VDDIO | A[6] | MOSCOU | VDDOSC | VSSIO | A |
| B | nCS[5] | VDDIO | nCS[3] | nMOE | VDDIO | N/C | DD[2] | CL[1] | VDDCORE | D[1] | A[2] | A[4] | A[5] | WAKEUP | VDDIO | nURESET | B |
| C | VDDIO | EXPCLK | VSSIO | VDDIO | VSSIO | VSSIO | VSSIO | VDDIO | VSSIO | VSSIO | VSSIO | VDDIO | VSSIO | VSSIO | nPOR | nEXTPWR | C |
| D | WRITE | EXPRDY | VSSIO | VDDIO | nCS[2] | nMWE | N/C | CL[2] | VSSRTC | D[4] | nPWRFL | MOSCIN | VDDIO | VSSIO | D[7] | D[8] | D |
| E | RXD[2] | PB[7] | TDI | WORD | VSSIO | nCS[0] | N/C | FRM | A[0] | D[5] | VSSOSC | VSSIO | nMEDCHG/ nBROM | VDDIO | D[9] | D[10] | E |
| F | PB[5] | PB[3] | VSSIO | TXD[2] | RUN/ CLKEN | VSSIO | N/C | DD[3] | A[1] | D[6] | VSSRTC | BATOK | nBATCHG | VSSIO | D[11] | VDDIO | F |
| G | PB[1] | VDDIO | TDO | PB[4] | PB[6] | VSSRTC | VSSRTC | DD[0] | D[3] | VSSRTC | A[7] | A[8] | A[9] | VSSIO | D[12] | D[13] | G |
| H | PA[7] | PA[5] | VSSIO | PA[4] | PA[6] | PB[0] | PB[2] | VSSRTC | VSSRTC | A[10] | A[11] | A[12] | A[13] | VSSIO | D[14] | D[15] | H |
| J | PA[3] | PA[1] | VSSIO | PA[2] | PA[0] | TXD[1] | CTS | VSSRTC | VSSRTC | A[17] | A[16] | A[15] | A[14] | nTRST | D[16] | D[17] | J |
| K | LEDDR | PHDIN | VSSIO | DCD | nTEST[1] | EINT[3] | VSSRTC | ADCIN | COL[4] | TCLK | D[20] | D[19] | D[18] | VSSIO | VDDIO | VDDIO | K |
| L | RXD[1] | DSR | VDDIO | nEINT[1] | PE[2]/ CLKSEL | VSSRTC | PD[0]/ LEDFLSH | VSSRTC | COL[6] | D[31] | VSSRTC | A[22] | A[21] | VSSIO | A[18] | A[19] | L |
| M | nTEST[0] | nEINT[2] | VDDIO | PE[0]/ BOOTSEL[0] | TMS | VDDIO | SSITXFR | DRIVE[1] | FB[0] | COL[0] | D[27] | VSSIO | A[23] | VDDIO | A[20] | D[21] | M |
| N | nEXTFIQ | PE[1]/ BOOTSEL[1] | VSSIO | VDDIO | PD[5] | PD[2] | SSIRXDA | ADCCLK | SMPCLK | COL[2] | D[29] | D[26] | HALFWORD | VSSIO | D[22] | D[23] | N |
| P | VSSRTC | RTCOU | VSSIO | VSSIO | VDDIO | VSSIO | VSSIO | VDDIO | VSSIO | VDDIO | VSSIO | VSSIO | VDDIO | VSSIO | D[24] | VDDIO | P |
| R | RTCIN | VDDIO | PD[4] | PD[1] | SSITXDA | nADCCS | VDDIO | ADCOUT | COL[7] | COL[3] | COL[1] | D[30] | A[27] | A[25] | VDDIO | A[24] | R |
| T | VDDRTC | PD[7] | PD[6] | PD[3] | SSICLK | SSIRXFR | VDDCORE | DRIVE[0] | FB[1] | COL[5] | VDDIO | BUZ | D[28] | A[26] | D[25] | VSSIO | T |

256-Ball PBGA Ball Listing

The list is ordered by ball location.

Table 20. 256-Ball PBGA Ball Listing

| Ball Location | Name | Type | Description |
|---------------|--------|-----------|-------------------------|
| A1 | VDDIO | Pad power | Digital I/O power, 3.3V |
| A2 | nCS[4] | O | Chip select out |
| A3 | nCS[1] | O | Chip select out |
| A4 | N/C | O | |
| A5 | N/C | O | |
| A6 | DD[1] | O | LCD serial display data |
| A7 | M | O | LCD AC bias drive |
| A8 | VDDIO | Pad power | Digital I/O power, 3.3V |
| A9 | D[0] | I/O | Data I/O |
| A10 | D[2] | I/O | Data I/O |
| A11 | A[3] | O | System byte address |

Table 20. 256-Ball PBGA Ball Listing (Continued)

| Ball Location | Name | Type | Description |
|---------------|--------|------------------|---------------------------|
| A12 | VDDIO | Pad power | Digital I/O power, 3.3V |
| A13 | A[6] | O | System byte address |
| A14 | MOSCOU | O | Main oscillator out |
| A15 | VDDOSC | Oscillator power | Oscillator power in, 2.5V |
| A16 | VSSIO | Pad ground | I/O ground |
| B1 | nCS[5] | O | Chip select out |
| B2 | VDDIO | Pad power | I/O ground |
| B3 | nCS[3] | O | Chip select out |
| B4 | nMOE | O | ROM, expansion OP enable |
| B5 | VDDIO | Pad power | Digital I/O power, 3.3V |
| B6 | N/C | O | |

Table 20. 256-Ball PBGA Ball Listing (Continued)

| Ball Location | Name | Type | Description |
|---------------|---------|-------------|-----------------------------------|
| B7 | DD[2] | O | LCD serial display data |
| B8 | CL[1] | O | LCD line clock |
| B9 | VDDCORE | Core power | Digital core power, 2.5V |
| B10 | D[1] | I/O | Data I/O |
| B11 | A[2] | O | System byte address |
| B12 | A[4] | O | System byte address |
| B13 | A[5] | O | System byte address |
| B14 | WAKEUP | I | System wake up input |
| B15 | VDDIO | Pad power | Digital I/O power, 3.3V |
| B16 | nURESET | I | User reset input |
| C1 | VDDIO | Pad power | Digital I/O power, 3.3V |
| C2 | EXPCLK | I | Expansion clock input |
| C3 | VSSIO | Pad ground | I/O ground |
| C4 | VDDIO | Pad power | Digital I/O power, 3.3V |
| C5 | VSSIO | Pad ground | I/O ground |
| C6 | VSSIO | Pad ground | I/O ground |
| C7 | VSSIO | Pad ground | I/O ground |
| C8 | VDDIO | Pad power | Digital I/O power, 3.3V |
| C9 | VSSIO | Pad ground | I/O ground |
| C10 | VSSIO | Pad ground | I/O ground |
| C11 | VSSIO | Pad ground | I/O ground |
| C12 | VDDIO | Pad power | Digital I/O power, 3.3V |
| C13 | VSSIO | Pad ground | I/O ground |
| C14 | VSSIO | Pad ground | I/O ground |
| C15 | nPOR | I | Power-on reset input |
| C16 | nEXTPWR | I | External power supply sense input |
| D1 | WRITE | O | Transfer direction |
| D2 | EXPRDY | I | Expansion port ready input |
| D3 | VSSIO | Pad ground | I/O ground |
| D4 | VDDIO | Pad power | Digital I/O power, 3.3V |
| D5 | nCS[2] | O | Chip select out |
| D6 | nMWE | O | ROM, expansion write enable |
| D7 | N/C | O | |
| D8 | CL[2] | O | LCD pixel clock out |
| D9 | VSSRTC | Core ground | Real time clock ground |
| D10 | D[4] | I/O | Data I/O |
| D11 | nPWRFL | I | Power fail sense input |
| D12 | MOSCIN | I | Main oscillator input |
| D13 | VDDIO | Pad power | Digital I/O power, 3.3V |
| D14 | VSSIO | Pad ground | I/O ground |
| D15 | D[7] | I/O | Data I/O |
| D16 | D[8] | I/O | Data I/O |
| E1 | RXD[2] | I | UART 2 receive data input |
| E2 | PB[7] | I | GPIO port B |
| E3 | TDI | I | JTAG data input |
| E4 | WORD | O | Word access select output |
| E5 | VSSIO | Pad ground | I/O ground |
| E6 | nCS[0] | O | Chip select out |

Table 20. 256-Ball PBGA Ball Listing (Continued)

| Ball Location | Name | Type | Description |
|---------------|---------------|-------------------|---|
| E7 | N/C | O | |
| E8 | FRM | O | LCD frame synchronization pulse |
| E9 | A[0] | O | System byte address |
| E10 | D[5] | I/O | Data I/O |
| E11 | VSSOSC | Oscillator ground | PLL ground |
| E12 | VSSIO | Pad ground | I/O ground |
| E13 | nMEDCHG/nBROM | I | Media change interrupt input / internal rom boot enable |
| E14 | VDDIO | Pad power | Digital I/O power, 3.3V |
| E15 | D[9] | I/O | Data I/O |
| E16 | D[10] | I/O | Data I/O |
| F1 | PB[5] | I | GPIO port B |
| F2 | PB[3] | I | GPIO port B |
| F3 | VSSIO | Pad ground | I/O ground |
| F4 | TXD[2] | O | UART 2 transmit data output |
| F5 | RUN/CLKEN | O | Run output / clock enable output |
| F6 | VSSIO | Pad ground | I/O ground |
| F7 | N/C | O | |
| F8 | DD[3] | O | LCD serial display data |
| F9 | A[1] | O | System byte address |
| F10 | D[6] | I/O | Data I/O |
| F11 | VSSRTC | RTC ground | Real time clock ground |
| F12 | BATOK | I | Battery ok input |
| F13 | nBATCHG | I | Battery changed sense input |
| F14 | VSSIO | Pad ground | I/O ground |
| F15 | D[11] | I/O | Data I/O |
| F16 | VDDIO | Pad power | Digital I/O power, 3.3V |
| G1 | PB[1]/PRDY[2] | I | GPIO port B / CL-PS6700 interface signal |
| G2 | VDDIO | Pad power | Digital I/O power, 3.3V |
| G3 | TDO | O | JTAG data out |
| G4 | PB[4] | I | GPIO port B |
| G5 | PB[6] | I | GPIO port B |
| G6 | VSSRTC | Core ground | Real time clock ground |
| G7 | VSSRTC | RTC ground | Real time clock ground |
| G8 | DD[0] | O | LCD serial display data |
| G9 | D[3] | I/O | Data I/O |
| G10 | VSSRTC | RTC ground | Real time clock ground |
| G11 | A[7] | O | System byte address |
| G12 | A[8] | O | System byte address |
| G13 | A[9] | O | System byte address |
| G14 | VSSIO | Pad ground | I/O ground |
| G15 | D[12] | I/O | Data I/O |
| G16 | D[13] | I/O | Data I/O |
| H1 | PA[7] | I | GPIO port A |
| H2 | PA[5] | I | GPIO port A |
| H3 | VSSIO | Pad ground | I/O ground |
| H4 | PA[4] | I | GPIO port A |
| H5 | PA[6] | I | GPIO port A |

Table 20. 256-Ball PBGA Ball Listing (Continued)

| Ball Location | Name | Type | Description |
|---------------|---------------|------------|--|
| H6 | PB[0]/PRDY[1] | I | GPIO port B / CL-PS6700 interface signal |
| H7 | PB[2] | I | GPIO port B |
| H8 | VSSRTC | RTC ground | Real time clock ground |
| H9 | VSSRTC | RTC ground | Real time clock ground |
| H10 | A[10] | O | System byte address |
| H11 | A[11] | O | System byte address |
| H12 | A[12] | O | System byte address |
| H13 | A[13] | O | System byte address |
| H14 | VSSIO | Pad ground | I/O ground |
| H15 | D[14] | I/O | Data I/O |
| H16 | D[15] | I/O | Data I/O |
| J1 | PA[3] | I | GPIO port A |
| J2 | PA[1] | I | GPIO port A |
| J3 | VSSIO | Pad ground | I/O ground |
| J4 | PA[2] | I | GPIO port A |
| J5 | PA[0] | I | GPIO port A |
| J6 | TXD[1] | O | UART 1 transmit data out |
| J7 | CTS | I | UART 1 clear to send input |
| J8 | VSSRTC | RTC ground | Real time clock ground |
| J9 | VSSRTC | RTC ground | Real time clock ground |
| J10 | A[17] | O | System byte address |
| J11 | A[16] | O | System byte address |
| J12 | A[15] | O | System byte address |
| J13 | A[14] | O | System byte address |
| J14 | nTRST | I | JTAG async reset input |
| J15 | D[16] | I/O | Data I/O |
| J16 | D[17] | I/O | Data I/O |
| K1 | LEDDRV | O | IR LED driver |
| K2 | PHDIN | I | Photodiode input |
| K3 | VSSIO | Pad ground | I/O ground |
| K4 | DCD | I | UART 1 data carrier detect |
| K5 | nTEST[1] | I | Test mode select input |
| K6 | EINT[3] | I | External interrupt |
| K7 | VSSRTC | RTC ground | Real time clock ground |
| K8 | ADCIN | I | SSI1 ADC serial input |
| K9 | COL[4] | O | Keyboard scanner column drive |
| K10 | TCLK | I | JTAG clock |
| K11 | D[20] | I/O | Data I/O |
| K12 | D[19] | I/O | Data I/O |
| K13 | D[18] | I/O | Data I/O |
| K14 | VSSIO | Pad ground | I/O ground |
| K15 | VDDIO | Pad power | Digital I/O power, 3.3V |
| K16 | VDDIO | Pad power | Digital I/O power, 3.3V |
| L1 | RXD[1] | I | UART 1 receive data input |
| L2 | DSR | I | UART 1 data set ready input |
| L3 | VDDIO | Pad power | Digital I/O power, 3.3V |
| L4 | nEINT[1] | I | External interrupt input |
| L5 | PE[2]/CLKSEL | I | GPIO port E / clock input mode select |

Table 20. 256-Ball PBGA Ball Listing (Continued)

| Ball Location | Name | Type | Description |
|---------------|------------------|-------------|-----------------------------------|
| L6 | VSSRTC | RTC ground | Real time clock ground |
| L7 | PD[0]/LEDFLSH | I/O | GPIO port D / LED blinker output |
| L8 | VSSRTC | Core ground | Real time clock ground |
| L9 | COL[6] | O | Keyboard scanner column drive |
| L10 | D[31] | I/O | Data I/O |
| L11 | VSSRTC | RTC ground | Real time clock ground |
| L12 | A[22] | O | System byte address |
| L13 | A[21] | O | System byte address |
| L14 | VSSIO | Pad ground | I/O ground |
| L15 | A[18] | O | System byte address |
| L16 | A[19] | O | System byte address |
| M1 | nTEST[0] | I | Test mode select input |
| M2 | nEINT[2] | I | External interrupt input |
| M3 | VDDIO | Pad power | Digital I/O power, 3.3V |
| M4 | PE[0]/BOOTSEL[0] | I | GPIO port E / Boot mode select |
| M5 | TMS | I | JTAG mode select |
| M6 | VDDIO | Pad power | Digital I/O power, 3.3V |
| M7 | SSITXFR | I/O | DAI/CODEC/SSI2 frame sync |
| M8 | DRIVE[1] | I/O | PWM drive output |
| M9 | FB[0] | I | PWM feedback input |
| M10 | COL[0] | O | Keyboard scanner column drive |
| M11 | D[27] | I/O | Data I/O |
| M12 | VSSIO | Pad ground | I/O ground |
| M13 | A[23] | O | System byte address |
| M14 | VDDIO | Pad power | Digital I/O power, 3.3V |
| M15 | A[20] | O | System byte address |
| M16 | D[21] | I/O | Data I/O |
| N1 | nEXTFIQ | I | External fast interrupt input |
| N2 | PE[1]/BOOTSEL[1] | I | GPIO port E / boot mode select |
| N3 | VSSIO | Pad ground | I/O ground |
| N4 | VDDIO | Pad power | Digital I/O power, 3.3V |
| N5 | PD[5] | I/O | GPIO port D |
| N6 | PD[2] | I/O | GPIO port D |
| N7 | SSIRXDA | I/O | DAI/CODEC/SSI2 serial data input |
| N8 | ADCCLK | O | SSI1 ADC serial clock |
| N9 | SMPCLK | O | SSI1 ADC sample clock |
| N10 | COL[2] | O | Keyboard scanner column drive |
| N11 | D[29] | I/O | Data I/O |
| N12 | D[26] | I/O | Data I/O |
| N13 | HALFWORD | O | Halfword access select output |
| N14 | VSSIO | Pad ground | I/O ground |
| N15 | D[22] | I/O | Data I/O |
| N16 | D[23] | I/O | Data I/O |
| P1 | VSSRTC | RTC ground | Real time clock ground |
| P2 | RTCOUT | O | Real time clock oscillator output |
| P3 | VSSIO | Pad ground | I/O ground |
| P4 | VSSIO | Pad ground | I/O ground |
| P5 | VDDIO | Pad power | Digital I/O power, 3.3V |

Table 20. 256-Ball PBGA Ball Listing (Continued)

| Ball Location | Name | Type | Description |
|---------------|----------|------------|-----------------------------------|
| P6 | VSSIO | Pad ground | I/O ground |
| P7 | VSSIO | Pad ground | I/O ground |
| P8 | VDDIO | Pad power | Digital I/O power, 3.3V |
| P9 | VSSIO | Pad ground | I/O ground |
| P10 | VDDIO | Pad power | Digital I/O power, 3.3V |
| P11 | VSSIO | Pad ground | I/O ground |
| P12 | VSSIO | Pad ground | I/O ground |
| P13 | VDDIO | Pad power | Digital I/O power |
| P14 | VSSIO | Pad ground | I/O ground |
| P15 | D[24] | I/O | Data I/O |
| P16 | VDDIO | Pad power | Digital I/O power, 3.3V |
| R1 | RTCIN | I/O | Real time clock oscillator input |
| R2 | VDDIO | Pad power | Digital I/O power, 3.3V |
| R3 | PD[4] | I/O | GPIO port D |
| R4 | PD[1] | I/O | GPIO port D |
| R5 | SSITXDA | O | DAI/CODEC/SSI2 serial data output |
| R6 | nADCCS | O | SSI1 ADC chip select |
| R7 | VDDIO | Pad power | Digital I/O power, 3.3V |
| R8 | ADCOUT | O | SSI1 ADC serial data output |
| R9 | COL[7] | O | Keyboard scanner column drive |
| R10 | COL[3] | O | Keyboard scanner column drive |
| R11 | COL[1] | O | Keyboard scanner column drive |
| R12 | D[30] | I/O | Data I/O |
| R13 | A[27] | O | System byte address |
| R14 | A[25] | O | System byte address |
| R15 | VDDIO | Pad power | Digital I/O power, 3.3V |
| R16 | A[24] | O | System byte address |
| T1 | VDDRRTC | RTC power | Real time clock power, 2.5V |
| T2 | PD[7] | I/O | GPIO port D |
| T3 | PD[6] | I/O | GPIO port D |
| T4 | PD[3] | I/O | GPIO port D |
| T5 | SSICLK | I/O | DAI/CODEC/SSI2 serial clock |
| T6 | SSIRXFR | – | DAI/CODEC/SSI2 frame sync |
| T7 | VDDCORE | Core power | Core power, 2.5V |
| T8 | DRIVE[0] | I/O | PWM drive output |
| T9 | FB[1] | I | PWM feedback input |
| T10 | COL[5] | O | Keyboard scanner column drive |
| T11 | VDDIO | Pad power | Digital I/O power, 3.3V |
| T12 | BUZ | O | Buzzer drive output |
| T13 | D[28] | I/O | Data I/O |
| T14 | A[26] | O | System byte address |
| T15 | D[25] | I/O | Data I/O |
| T16 | VSSIO | Pad ground | I/O ground |

JTAG Boundary Scan Signal Ordering

Table 21. JTAG Boundary Scan Signal Ordering

| LQFP Pin No. | PBGA Ball | Signal | Type | Position |
|--------------|-----------|-------------|------|----------|
| 1 | B1 | nCS[5] | O | 1 |
| 4 | C2 | EXPCLK | I/O | 3 |
| 5 | E4 | WORD | O | 6 |
| 6 | D1 | WRITE | O | 8 |
| 7 | F5 | RUN/CLKEN | O | 10 |
| 8 | D2 | EXPRDY | I | 13 |
| 9 | F4 | TXD2 | O | 14 |
| 10 | E1 | RXD2 | I | 16 |
| 13 | E2 | PB[7] | I/O | 17 |
| 14 | G5 | PB[6] | I/O | 20 |
| 15 | F1 | PB[5] | I/O | 23 |
| 16 | G4 | PB[4] | I/O | 26 |
| 17 | F2 | PB[3] | I/O | 29 |
| 18 | H7 | PB[2] | I/O | 32 |
| 19 | G1 | PB[1]/PRDY2 | I/O | 35 |
| 20 | H6 | PB[0]/PRDY1 | I/O | 38 |
| 23 | H1 | PA[7] | I/O | 41 |
| 24 | H5 | PA[6] | I/O | 44 |
| 25 | H2 | PA[5] | I/O | 47 |
| 26 | H4 | PA[4] | I/O | 50 |
| 27 | J1 | PA[3] | I/O | 53 |
| 28 | J4 | PA[2] | I/O | 56 |
| 29 | J2 | PA[1] | I/O | 59 |
| 30 | J5 | PA[0] | I/O | 62 |
| 31 | K1 | LEDDR | O | 65 |
| 32 | J6 | TXD1 | O | 67 |
| 34 | K2 | PHDIN | I | 69 |
| 35 | J7 | CTS | I | 70 |
| 36 | L1 | RXD1 | I | 71 |
| 37 | K4 | DCD | I | 72 |
| 38 | L2 | DSR | I | 73 |
| 39 | K5 | nTEST1 | I | 74 |
| 40 | M1 | nTEST0 | I | 75 |
| 41 | K6 | EINT3 | I | 76 |
| 42 | M2 | nEINT2 | I | 77 |
| 43 | L4 | nEINT1 | I | 78 |

Table 21. JTAG Boundary Scan Signal Ordering (Continued)

| LQFP Pin No. | PBGA Ball | Signal | Type | Position |
|-------------------------|----------------------|----------------|-------------|-----------------|
| 44 | N1 | nEXTFIQ | I | 79 |
| 45 | L5 | PE[2]/CLKSEL | I/O | 80 |
| 46 | N2 | PE[1]/BOOTSEL1 | I/O | 83 |
| 47 | M4 | PE[0]/BOOTSEL0 | I/O | 86 |
| 53 | T2 | PD[7] | I/O | 89 |
| 54 | T3 | PD[6] | I/O | 92 |
| 55 | N5 | PD[5] | I/O | 95 |
| 56 | R3 | PD[4] | I/O | 98 |
| 59 | T4 | PD[3] | I/O | 101 |
| 60 | N6 | PD[2] | I/O | 104 |
| 61 | R4 | PD[1] | I/O | 107 |
| 62 | L7 | PD[0]/LEDFLSH | O | 110 |
| 68 | T6 | SSIRXFR | I/O | 122 |
| 69 | K8 | ADCIN | I | 125 |
| 70 | R6 | nADCCS | O | 126 |
| 75 | M8 | DRIVE1 | I/O | 128 |
| 76 | T8 | DRIVE0 | I/O | 131 |
| 77 | N8 | ADCCLK | O | 134 |
| 78 | R8 | ADCOUT | O | 136 |
| 79 | N9 | SMPCLK | O | 138 |
| 80 | T9 | FB1 | I | 140 |
| 82 | M9 | FB0 | I | 141 |
| 83 | R9 | COL7 | O | 142 |
| 84 | L9 | COL6 | O | 144 |
| 85 | T10 | COL5 | O | 146 |
| 86 | K9 | COL4 | O | 148 |
| 87 | R10 | COL3 | O | 150 |
| 88 | N10 | COL2 | O | 152 |
| 91 | R11 | COL1 | O | 154 |
| 92 | M10 | COL0 | O | 156 |
| 93 | T12 | BUZ | O | 158 |
| 94 | L10 | D[31] | I/O | 160 |
| 95 | R12 | D[30] | I/O | 163 |
| 96 | N11 | D[29] | I/O | 166 |
| 97 | T13 | D[28] | I/O | 169 |
| 99 | R13 | A[27] | Out | 172 |
| 100 | M11 | D[27] | I/O | 174 |
| 101 | T14 | A[26] | O | 177 |

Table 21. JTAG Boundary Scan Signal Ordering (Continued)

| LQFP Pin No. | PBGA Ball | Signal | Type | Position |
|--------------|-----------|----------|------|----------|
| 102 | N12 | D[26] | I/O | 179 |
| 103 | R14 | A[25] | O | 182 |
| 104 | T15 | D[25] | I/O | 184 |
| 105 | N13 | HALFWORD | O | 187 |
| 106 | R16 | A[24] | O | 189 |
| 109 | P15 | D[24] | I/O | 191 |
| 110 | M13 | A[23] | O | 194 |
| 111 | N16 | D[23] | I/O | 196 |
| 112 | L12 | A[22] | O | 199 |
| 113 | N15 | D[22] | I/O | 201 |
| 114 | L13 | A[21] | O | 204 |
| 115 | M16 | D[21] | I/O | 206 |
| 117 | M15 | A[20] | O | 209 |
| 118 | K11 | D[20] | I/O | 211 |
| 119 | L16 | A[19] | O | 214 |
| 120 | K12 | D[19] | I/O | 216 |
| 121 | L15 | A[18] | O | 219 |
| 122 | K13 | D[18] | I/O | 221 |
| 126 | J10 | A[17] | O | 224 |
| 127 | J16 | D[17] | I/O | 226 |
| 128 | J11 | A[16] | O | 229 |
| 129 | J15 | D[16] | I/O | 231 |
| 130 | J12 | A[15] | O | 234 |
| 131 | H16 | D[15] | I/O | 236 |
| 132 | J13 | A[14] | O | 239 |
| 133 | H15 | D[14] | I/O | 241 |
| 134 | H13 | A[13] | O | 244 |
| 135 | G16 | D[13] | I/O | 246 |
| 136 | H12 | A[12] | O | 249 |
| 137 | G15 | D[12] | I/O | 251 |
| 138 | H11 | A[11] | O | 254 |
| 141 | F15 | D[11] | I/O | 256 |
| 142 | H10 | A[10] | O | 259 |
| 143 | E16 | D[10] | I/O | 261 |
| 144 | G13 | A[9] | O | 264 |
| 145 | E15 | D[9] | I/O | 266 |
| 146 | G12 | A[8] | O | 269 |
| 147 | D16 | D[8] | I/O | 271 |

Table 21. JTAG Boundary Scan Signal Ordering (Continued)

| LQFP Pin No. | PBGA Ball | Signal | Type | Position |
|-------------------------|----------------------|---------------|-------------|-----------------|
| 148 | G11 | A[7] | O | 274 |
| 150 | D15 | D[7] | I/O | 276 |
| 151 | F13 | nBATCHG | I | 279 |
| 152 | C16 | nEXTPWR | I | 280 |
| 153 | F12 | BATOK | I | 281 |
| 154 | C15 | nPOR | I | 282 |
| 155 | E13 | nMEDCHG/nBROM | I | 283 |
| 156 | B16 | nURESET | I | 284 |
| 161 | B14 | WAKEUP | I | 285 |
| 162 | D11 | nPWRFL | I | 286 |
| 163 | A13 | A[6] | O | 287 |
| 164 | F10 | D[6] | I/O | 289 |
| 165 | B13 | A[5] | O | 292 |
| 166 | E10 | D[5] | I/O | 294 |
| 169 | B12 | A[4] | O | 297 |
| 170 | D10 | D[4] | I/O | 299 |
| 171 | A11 | A[3] | O | 302 |
| 172 | G9 | D[3] | I/O | 304 |
| 173 | B11 | A[2] | O | 307 |
| 175 | A10 | D[2] | I/O | 309 |
| 176 | F9 | A[1] | O | 312 |
| 177 | B10 | D[1] | I/O | 314 |
| 178 | E9 | A[0] | O | 317 |
| 179 | A9 | D[0] | I/O | 319 |
| 184 | D8 | CL2 | O | 322 |
| 185 | B8 | CL1 | O | 324 |
| 186 | E8 | FRM | O | 326 |
| 187 | A7 | M | O | 328 |
| 188 | F8 | DD[3] | I/O | 330 |
| 189 | B7 | DD[2] | I/O | 333 |
| 191 | A6 | DD[1] | I/O | 336 |
| 192 | G8 | DD[0] | I/O | 339 |
| 193 | B6 | N/C | O | 342 |
| 194 | D7 | N/C | O | 344 |
| 195 | A5 | N/C | I/O | 346 |
| 196 | E7 | N/C | I/O | 349 |
| 199 | F7 | N/C | I/O | 352 |
| 200 | A4 | N/C | I/O | 355 |

Table 21. JTAG Boundary Scan Signal Ordering (Continued)

| LQFP Pin No. | PBGA Ball | Signal | Type | Position |
|--------------|-----------|--------|------|----------|
| 201 | D6 | nMWE | O | 358 |
| 202 | B4 | nMOE | O | 360 |
| 204 | E6 | nCS[0] | O | 362 |
| 205 | A3 | nCS[1] | O | 364 |
| 206 | D5 | nCS[2] | O | 366 |
| 207 | B3 | nCS[3] | O | 368 |
| 208 | A2 | nCS[4] | O | 370 |

- 1) See EP7309 Users' Manual for pin naming / functionality.
- 2) For each pad, the JTAG connection ordering is input, output, then enable as applicable.

CONVENTIONS

This section presents acronyms, abbreviations, units of measurement, and conventions used in this data sheet.

Acronyms and Abbreviations

Table 22 lists abbreviations and acronyms used in this data sheet.

Table 22. Acronyms and Abbreviations

| Acronym/ Abbreviation | Definition |
|--------------------------|-------------------------------------|
| A/D | analog-to-digital |
| ADC | analog-to-digital converter |
| CODEC | coder / decoder |
| D/A | digital-to-analog |
| DMA | direct-memory access |
| EPB | embedded peripheral bus |
| FCS | frame check sequence |
| FIFO | first in / first out |
| FIQ | fast interrupt request |
| GPIO | general purpose I/O |
| ICT | in circuit test |
| IR | infrared |
| IRQ | standard interrupt request |
| IrDA | Infrared Data Association |
| JTAG | Joint Test Action Group |
| LCD | liquid crystal display |
| LED | light-emitting diode |
| LQFP | low profile quad flat pack |
| LSB | least significant bit |
| MIPS | millions of instructions per second |
| MMU | memory management unit |
| MSB | most significant bit |
| PBGA | plastic ball grid array |
| PCB | printed circuit board |
| PDA | personal digital assistant |
| PLL | phase locked loop |
| p/u | pull-up resistor |
| RISC | reduced instruction set computer |
| RTC | Real-Time Clock |
| SIR | slow (9600–115.2 kbps) infrared |
| SRAM | static random access memory |
| SSI | synchronous serial interface |

Table 22. Acronyms and Abbreviations (Continued)

| Acronym/ Abbreviation | Definition |
|--------------------------|---------------------------------|
| TAP | test access port |
| TLB | translation lookaside buffer |
| UART | universal asynchronous receiver |

Units of Measurement

Table 23. Unit of Measurement

| Symbol | Unit of Measure |
|--------|--------------------------------------|
| °C | degree Celsius |
| fs | sample frequency |
| Hz | hertz (cycle per second) |
| kbps | kilobits per second |
| KB | kilobyte (1,024 bytes) |
| kHz | kilohertz |
| kΩ | kilohm |
| Mbps | megabits (1,048,576 bits) per second |
| MB | megabyte (1,048,576 bytes) |
| MBps | megabytes per second |
| MHz | megahertz (1,000 kilohertz) |
| μA | microampere |
| μF | microfarad |
| μW | microwatt |
| μs | microsecond (1,000 nanoseconds) |
| mA | milliampere |
| mW | milliwatt |
| ms | millisecond (1,000 microseconds) |
| ns | nanosecond |
| V | volt |
| W | watt |

General Conventions

Hexadecimal numbers are presented with all letters in uppercase and a lowercase “h” appended or with a 0x at the beginning. For example, 0x14 and 03CAh are hexadecimal numbers. Binary numbers are enclosed in single quotation marks when in text (for example, ‘11’ designates a binary number). Numbers not indicated by an “h”, 0x or quotation marks are decimal.

Registers are referred to by acronym, with bits listed in brackets separated by a colon (:) (for example, CODR[7:0]), and are described in the EP7309 User’s Manual. The use of “TBD” indicates values that are “to be determined,” “n/a” designates “not available,” and “n/c” indicates a pin that is a “no connect.”

Pin Description Conventions

Abbreviations used for signal directions are listed in Table 24.

Table 24. Pin Description Conventions

| Abbreviation | Direction |
|--------------|-----------------|
| I | Input |
| O | Output |
| I/O | Input or Output |

Ordering Information

| Model | Temperature | Package |
|------------|---------------|---------------------------|
| EP7309-CBZ | 0 to +70 °C | 256-pin PBGA, 17mm X 17mm |
| EP7309-IBZ | -40 to +85 °C | |
| EP7309-CVZ | 0 to +70 °C | 208-pin LQFP. |
| EP7309-IVZ | -40 to +85 °C | |

Environmental, Manufacturing, & Handling Information

| Model Number | Peak Reflow Temp | MSL Rating* | Max Floor Life |
|--------------|------------------|-------------|----------------|
| EP7309-CBZ | 260 °C | 3 | 7 Days |
| EP7309-IBZ | | | |
| EP7309-CVZ | | | |
| EP7309-IVZ | | | |

* MSL (Moisture Sensitivity Level) as specified by IPC/JEDEC J-STD-020.

All devices are now lead (Pb) free.

Revision History

| Revision | Date | Changes |
|----------|----------|--|
| PP1 | NOV 2003 | First preliminary release. |
| F1 | AUG 2005 | Updated ordering information. Added MSL data. |
| F2 | MAR 2011 | Removed lead-containing device ordering information. Removed 204-pin BGA option. |

Contacting Cirrus Logic Support

For all product questions and inquiries contact a Cirrus Logic Sales Representative.

To find the one nearest to you go to www.cirrus.com

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